

MOS INTEGRATED CIRCUIT μ PD784915

16-BIT SINGLE-CHIP MICROCONTROLLER

DESCRIPTION

The μ PD784915 is a member of the NEC 78K/IV Series of microcontrollers equipped with a high-speed 16-bit CPU and a successor to the 78K/I Series 8-bit single-chip microcontrollers for VCR software servo control.

The μ PD784915 contains many peripheral hardware units ideal for VCR control, such as a multi-function timer unit (super timer unit) best-suited to software servo control and VCR analog circuits.

A one-time PROM model of the μ PD784915, the μ PD78P4916, is also available.

The functions of the μ PD784915 are described in detail in the following User's Manual. Be sure to read this manual before designing your system.

 μ PD784915 Subseries User's Manual - Hardware: U10444E 78K/IV Series User's Manual - Instruction : U10905E

FEATURES

- High instruction execution speed realized by 16-bit CPU core
 - · Minimum instruction execution time: 250 ns (with 8-MHz internal clock)
- · High internal memory capacity
 - · ROM: 48K bytes
 - RAM: 1280 bytes
- · VCR analog circuits conforming to VHS Standard
 - · CTL amplifier
 - · RECCTL driver (rewritable)
 - CFG amplifier
 - · DFG amplifier
 - DPG comparator
 - DPFG separation circuit (ternary separation circuit)
 - Reel FG comparator (2 channels)
 - CSYNC comparator
- · Timer unit (super timer unit) for servo control
- Serial interface: 2 channels (3-line serial I/O)
- A/D converter: 12 channels (conversion time: 10 μs)
- Low-frequency oscillation mode: main system clock frequency = internal clock frequency
- Low-power consumption mode: CPU can operate with a subsystem clock.
- Supply voltage range: VDD = 2.7 to 5.5 V
- Hardware watch function: watch operation at low voltage (VDD = 2.7 V (MIN.)) and low current

APPLICATIONS

To control system/servo/timer of VCR

The information in this document is subject to change without notice.

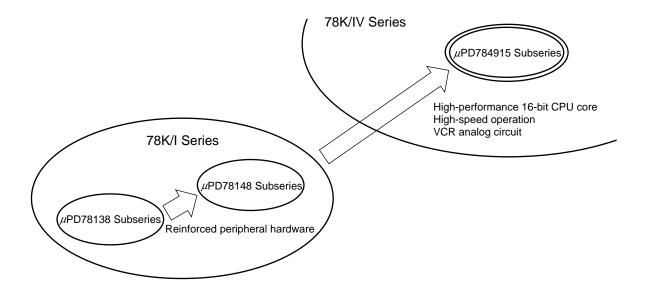


ORDERING INFORMATION

Part No.	Package
μPD784915GF-xxx-3BA	100-pin plastic QFP (14 x 20 mm)

Remark xxx indicates a ROM code number.

Product Development of 78K/IV Series





Function List (1/2)

Item Function						
Internal	I ROM capacity	48K bytes				
	I RAM capacity	1280 bytes				
	ing clock	16 MHz (interna	l clock: 8 MHz)			
	3		scillation mode: 8 M	/IHz (internal clock:	: 8 MHz)	
			umption mode: 32.7		•	
Minimu	m instruction	-	1Hz internal system			
	on time			,		
I/O port		(input: 8				
		54 { I/O : 46				
Real-tir	ne output port		e each for pseudo	Vsync. head amplif	fier switch, and ch	rominance
		rotation)			,	
	Timer/counter	Timer/counter	Compare register	Capture register	r Remark	
		TM0 (16 bits)	3			
		TM1 (16 bits)	3	1		
		FRC (22 bits)	_	6		
		TM3 (16 bits)	2	1		
		UDC (5 bits)	1	_		
		EC (8 bits)	4	– F	or HSW signal ge	neration
		EDV (8 bits)	1	_	For CFG signal d	
	Capture register	Input signal	Number of bits	Measurable cycle	Operating edg	e
		CFG	22	125 ns to 524 ms	\uparrow \downarrow	
		DFG	22	125 ns to 524 ms	\uparrow	
0		HSW	16	1 μ s to 65.5 ms	\uparrow \downarrow	
Super timer		Vsync	22	125 ns to 524 ms	\uparrow	
		CTL	16	1 μ s to 65.5 ms	\uparrow \downarrow	
unit		TREEL	22	125 ns to 524 ms	\uparrow \downarrow	
		Sreel	22	125 ns to 524 ms	\uparrow \downarrow	
	VCR special circuit	Vsync separati	on circuit, Hayne sep	paration circuit		
		VISS detection	n, wide aspect detec	ction circuits		
		Field identification	ition circuit			
		Head amplifier	switch/chrominance	e rotation output ci	rcuit	
	General-purpose	Timer	Compare re	gister Ca	apture register	
	timer	TM2 (16 bits)	1		-	
		TM4 (16 bits)	1 (capture/co	mpare)	1	
		TM5 (16 bits)	1		-	
	PWM output	16-bit resolution	on: 3 channels (carr	ier frequency: 62.5	kHz)	
		8-bit resolution	n : 3 channels (carr	ier frequency: 62.5	5 kHz)	
Serial i	nterface	3-line serial I/O:	2 channels			
		BUSY/STRB c	control (1 channel or	nly)		
A/D cor	/D converter 8-bit resolution x 12 channels, conversion time: 10 μ s					



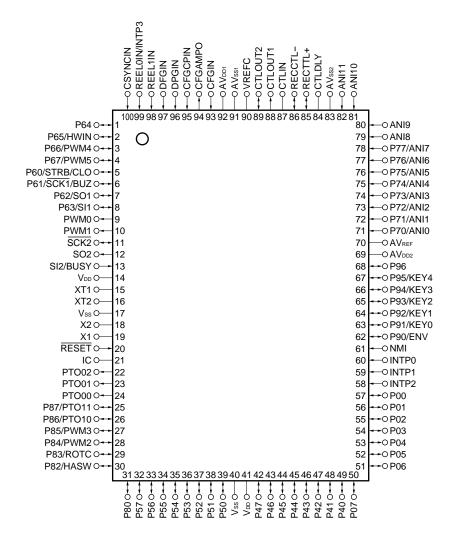
Function List (2/2)

Item	Function			
Analog circuit	CTL amplifier			
	RECCTL driver (rewritable)			
	DFG amplifier, DPG comparator, CFG amplifier			
	DPFG separation circuit (ternary separation circuit)			
	Reel FG comparator (2 channels)			
	CSYNC comparator			
Interrupt	4 levels (programmable), vector interrupt, macro service, context switching			
External sources	9 (including NMI)			
Internal sources	19 (including software interrupt)			
Standby function	HALT mode/STOP mode/low power consumption mode/low power consumption			
	HALT mode			
	STOP mode can be released by input of valid edge of NMI pin, watch interrupt (INTW),			
	or INTP1/INTP2/KEY0-KEY4 pins			
Watch function	0.5-second measurement, low-voltage operation (V _{DD} = 2.7 V)			
Supply voltage	V _{DD} = 2.7 to 5.5 V			
Package	100-pin plastic QFP (14 x 20 mm)			

*

PIN CONFIGURATION (Top View)

100-pin plastic QFP (14 x 20 mm)
 μPD784915GF-xxx-3BA



Caution Directly connect the IC (Internally Connected) pins to Vss.



ANIO-ANI11 : Analog Input P00-P07 : Port0 AVDD1, AVDD2 : Analog Power Supply P40-P47 : Port4 AVss₁, AVss₂ : Analog Ground : Port5 P50-P57 : Analog Reference Voltage **AV**REF P60-P67 : Port6 **BUSY** : Serial Busy P70-P77 : Port7 BUZ : Buzzer Output P80, P82-P87 : Port8 : Capstan FG Amplifier Output **CFGAMPO** P90-P96 : Port9

CFGCPIN : Capstan FG Capacitor Input PTO00-PTO02 : Programmable Timer Output

CFGIN : Analog Unit Input PTO10, PTO11

CLO : Clock Output PWM0-PWM5 : Pulse Width Modulation Output CSYNCIN : Analog Unit Input RECCTL+, RECCTL- : RECCTL Output/PBCLT Input

CTLDLY : Control Delay Input REEL0IN, REEL1IN : Analog Unit Input

CTLIN : CTL Amplifier Input Capacitor RESET : Reset

CTLOUT1, CTLOUT2: CTL Amplifier Output ROTC: Chrominance Rotate Output

SCK1, SCK2 **DFGIN** : Analog Unit Input : Serial Clock **DPGIN** : Analog Unit Input SI1, SI2 : Serial Input ENV : Envelope Input SO1, SO2 : Serial Output : Head Amplifier Switch Output **STRB** : Serial Strobe **HASW HWIN** : Hardware Timer External Input : Power Supply VDD

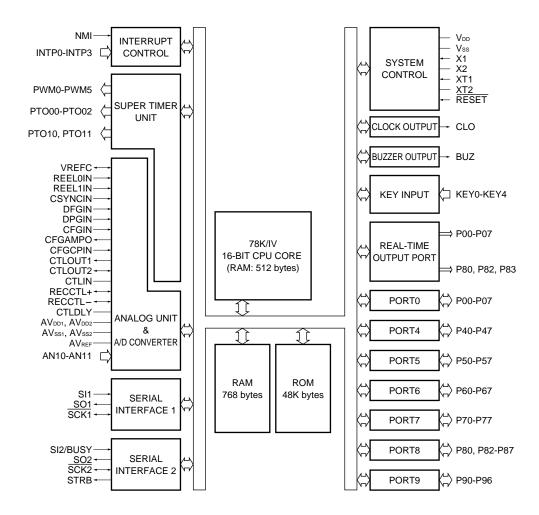
IC : Internally Connected VREFC : Reference Amplifier Capacitor

INTP0-INTP3 : Interrupt From Peripherals Vss : Ground

KEY0-KEY4 : Key Return X1, X2 : Crystal (Main System Clock)
NMI : Nonmaskable Interrupt XT1, XT2 : Crystal (Subsystem Clock)



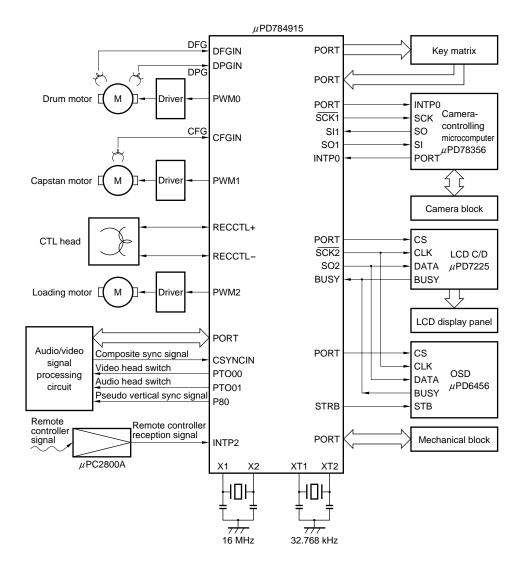
INTERNAL BLOCK DIAGRAM





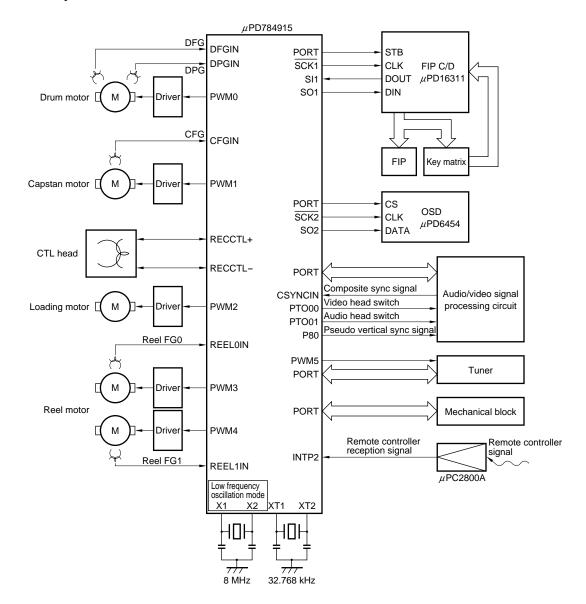
SYSTEM CONFIGURATION EXAMPLE

• Camera-contained VCR





Stationary VCR





CONTENTS

1.	DIFF	ERENCE AMONG μ PD784915 SUBSERIES PRODUCTS	11
2.	PIN I	FUNCTION	12
	2.1	PORT PINS	12
	2.2	PINS OTHER THAN PORT PINS	13
	2.3	I/O CIRCUITS AND PROCESSING OF UNUSED PINS	15
3.	INTE	RNAL BLOCK FUNCTION	19
	3.1	CPU REGISTERS	19
		3.1.1 General-Purpose Registers	19
		3.1.2 Other CPU Registers	20
	3.2	MEMORY SPACE	20
	3.3	SPECIAL FUNCTION REGISTERS (SFRs)	22
	3.4	PORTS	27
	3.5	REAL-TIME OUTPUT PORT	28
	3.6	SUPER TIMER UNIT	32
	3.7	SERIAL INTERFACE	37
	3.8	A/D CONVERTER	39
	3.9	VCR ANALOG CIRCUITS	40
	3.10	WATCH FUNCTION	46
	3.11	CLOCK OUTPUT FUNCTION	47
4.	INTE	ERNAL/EXTERNAL CONTROL FUNCTION	48
•	4.1	INTERRUPT FUNCTION	48
		4.1.1 Vectored Interrupt	50
		4.1.2 Context Switching	50
		4.1.3 Macro Service	51
		4.1.4 Application Example of Macro Service	53
	4.2	STANDBY FUNCTION	56
	4.3	CLOCK GENERATOR CIRCUIT	58
	4.4	RESET FUNCTION	59
5.	INST	RUCTION SET	60
6.	ELE	CTRICAL CHARACTERISTICS	64
7.	PAC	KAGE DRAWING	76
8.	REC	OMMENDED SOLDERING CONDITIONS	77
ΑP	PEND	DIX A. DEVELOPMENT TOOLS	78
۸ D	DENID	NV P. DELATED DOCUMENTS	90

 μ PD784915



\star 1. DIFFERENCE AMONG μ PD784915 SUBSERIES PRODUCTS

The μ PD784915 subseries comprises the four products shown in Table 1-1. The μ PD78P4916 is a product with the mask ROM of the μ PD784915 and 784916A replaced by a writable one-time PROM. Therefore, it has the same functions as those of the μ PD784915, 784915A, and 784916A, with only exception that it has PROM for internal ROM and a different capacity.

Before using the PROM to perform debugging or preproduction of an application system and then using the mask ROM to proceed with volume production, etc., thoroughly check the differences between these products.

For more information about the CPU functions and on-chip hardware, see μ PD784915 Subseries User's Manual - Hardware (U10444E).

Item	μPD784915, 784915A ^{Note 1}	μ PD784916A $^{ m Note~1}$	μPD78P4916				
Internal ROM	Mask ROM	Mask ROM	One-time PROM				
	48K bytes	62K bytes	62K bytesNote 2				
Internal RAM	1280 bytes	1280 bytes	2048 bytes ^{Note 2}				
Internal memory capacity	Not available	Not available	Available				
select register (IMS)							
Pin connections	The μPD78P4916 has add	The μ PD78P4916 has additional PROM write/read related pin functions.					
Other	Since these products are di	Since these products are different in circuit scale and mask layout, they partly differ					
	in noise resistance, noise radiation and electrical specifications.						

Table 1-1. Differences between μ PD784915 Subseries Products

Notes 1. Under development

2. The internal PROM and internal RAM capacities can be changed by the internal memory capacity select register (IMS).

Caution The PROM and mask ROM differ in noise resistance and noise radiation, etc. When considering replacement of a PROM product by a mask ROM product in the process from preproduction to volume production, perform sufficient evaluation using a CS product (not ES product) of the mask ROM product.

Remark The μ PD784915A, a process shrink version of the μ PD784915, can be supported at low cost.



2. PIN FUNCTION

2.1 PORT PINS

Pin Name	I/O	Shared with:		Function			
P00-P07	I/O	Real-time	8-bit I/o port (port 0).				
		output port	Can be set in input of	r output mode in 1-bit units.			
			Can be connected with software pull-up resistors (P00-P07).				
P40-P47	I/O	_	8-bit I/O port (port 4).				
			Can be set in input or output mode in 1-bit units.				
			Can be connected with	th software pull-up resistors (P40-P47).			
P50-P57	I/O	_	8-bit I/O port (port 5).				
			Can be set in input of	r output mode in 1-bit units.			
			Can be connected with	th software pull-up resistors (P50-P57).			
P60	I/O	STRB/CLO	8-bit I/O port (port 6).				
P61		SCK1/BUZ	Can be set in input of	r output mode in 1-bit units.			
P62		SO1	Can be connected with	th software pull-up resistors (P60-P67).			
P63		SI1					
P64		_					
P65		HWIN					
P66		PWM4					
P67		PWM5					
P70-P77	Input	ANI0-ANI7	8-bit input port (port 7)				
P80	I/O	Real-time	Pseudo Vsync output	7-bit I/O port (port 8).			
P82		output port	HASW output	Can be set in input or output mode in			
				1-bit units.			
P83			ROTC output	Can be connected with software pull-			
				up resistors (P80, P82-P87).			
P84		PWM2					
P85		PWM3					
P86		PTO10					
P87		PTO11					
P90	I/O	ENV	7-bit I/O port (port 9).				
P91-P95		KEY0-KEY4	Can be set in input of	r output mode in 1-bit units.			
P96		_	Can be connected with	th software pull-up resistors (P90-P97).			



2.2 PINS OTHER THAN PORT PINS (1/2)

Pin Name	I/O	Shared with:	Function
REELOIN	Input	INTP3	Reel FG input
REEL1IN		_	
DFGIN		_	Drum FG, PFG input (ternary)
DPGIN		-	Drum PG input
CFGIN		-	Capstan FG input
CSYNCIN		-	Composite SYNC input
CFGCPIN		_	CFG comparator input
CFGAMPO	Output	-	CFG amplifier output
PTO00	Output	_	Programmable timer output of super timer unit
PTO01		-	
PTO02		-	
PTO10		P86	
PTO11		P87	
PWM0	Output	-	PWM output of super timer unit
PWM1		_	
PWM2		P84	
PWM3		P85	
PWM4		P66	
PWM5		P67	
HASW	Output	P82	Head amplifier switch signal output
ROTC	Output	P83	Chrominance rotation signal output
ENV	Input	P90	Envelope signal input
SI1	Input	P63	Serial data input (serial interface channel 1)
SO1	Output	P62	Serial data output (serial interface channel 1)
SCK1	I/O	P61/BUZ	Serial clock I/O (serial interface channel 1)
SI2	Input	BUSY	Serial data input (serial interface channel 2)
SO2	Output	_	Serial data output (serial interface channel 2)
SCK2	I/O	_	Serial clock I/O (serial interface channel 2)
BUSY	Input	SI2	Serial busy signal input (serial interface channel 2)
STRB	Output	P60/CLO	Serial strobe signal output (serial interface channel 2)
ANI0-ANI7	Analog input	P70-P77	Analog signal input of A/D converter
ANI8-ANI11		_	
CTLIN	-	_	CTL amplifier input capacitor connection
CTLOUT1	Output	_	CTL amplifier output
CTLOUT2	I/O	_	Logic signal input/CTL amplifier output
RECCTL+, RECCTL-	I/O	_	RECCTL signal output/PBCTL signal input
CTLDLY	_	_	External time constant connection (for RECCTL rewriting)
VREFC	_	_	VREF amplifier AC connection
NMI	Input	_	Non-maskable interrupt request input
INTP0-INTP2	Input	_	External interrupt request input
INTP3	Input	REELOIN	1
KEY0-KEY4	Input	P91-P95	Key input signal input
CLO	Output	P60/STRB	Clock output
BUZ	Output	P61/SCK1	Buzzer output



2.2 PINS OTHER THAN PORT PINS (2/2)

Pin Name	I/O	Shared with:	Function
HWIN	Input	P65	External input of hardware watch counter
RESET	Input	_	Reset input
X1	Input	_	Crystal connection for main system clock oscillation
X2	_		
XT1	Input	_	Crystal connection for subsystem clock oscillation.
XT2	_		Crystal connection for watch clock oscillation
AVDD1, AVDD2	_	_	Positive power supply to analog circuits
AVss1, AVss2	_	_	GND of analog circuits
AVREF	_	_	Reference voltage input to A/D converter
V _{DD}	_	_	Positive power supply to digital circuits
Vss	_	_	GND of digital circuits
IC	_	_	Internally connected. Directly connect this pin to Vss.



2.3 I/O CIRCUITS AND PROCESSING OF UNUSED PINS

Table 2-1. shows the types of the I/O circuits of the respective pins and processing of the unused pins. Figure 2-1. shows the circuits of the respective types.

Table 2-1. I/O Circuits of Respective Pins and Processing of Unused Pins (1/2)

Pin	I/O Circuit Type	I/O	Recommended Connection of Unused Pins
P00-P07	5-A	I/O	Input: Connect to VDD
P40-P47			Output: Open
P50-P57			
P60/STRB/CLO			
P61/SCK1/BUZ	8-A		
P62/SO1	5-A		
P63/SI1	8-A		
P64	5-A		
P65/HWIN	8-A		
P66/PWM4	5-A		
P67/PWM5			
P70/ANI0-P77/ANI7	9	Input	Connect to Vss
P80	5-A	I/O	Input: Connect to VDD
P82/HASW			Output: Open
P83/ROTC			
P84/PWM2			
P85/PWM3			
P86/PTO10			
P87/PTO11			
P90/ENV			
P91/KEY0-P95/KEY4	8-A		
P96	5-A		
SI2/BUSY	2-A	Input	Connect to VDD
SO2	4	Output	Hi-Z: Connect to Vss via pull-down resistor
			Others: Open
SCK2	8-A	I/O	Input: Connect to VDD
			Output: Open
ANI8-ANI11	7	Input	Connect to Vss
RECCTL+, RECCTL-	-	I/O	When ENCTL = 0 and ENREC = 0: Connect to Vss

Remark ENCTL: bit 1 of amplifier control register (AMPC)

ENREC: bit 7 of amplifier mode register 0 (AMPM0)



Table 2-1. I/O Circuits of Respective Pins and Processing of Unused Pins (2/2)

Pin	I/O Circuit Type	I/O	Recommended Connection of Unused Pins
DFGIN	_	Input	When ENDRUM = 0: Connect to Vss
DPGIN			When ENDRUM=0 or ENDRUM=1 and SELPGSEPA
			= 0: Connect to Vss
CFGIN, CFGCPIN			When ENCAP = 0: Connect to Vss
CSYNCIN			When ENCSYN = 0: Connect to Vss
REEL0IN/INTP3, REEL1IN			When ENREEL = 0: Connect to Vss
CTLOUT1	-	Output	Open
CTLOUT2	_	I/O	When ENCTL = 0 and ENCOMP = 0: Connect to Vss
			When ENCTL = 1: Open
CFGAMPO	-	Output	Open
CTLIN	_	-	When ENCTL = 0: Open
VREFC			When ENCTL = 0 and ENCAP = 0 and ENCOMP =
			0: Open
CTLDLY			Open
PWM0, PWM1	3	Output	Open
PTO00-PTO02			
NMI	2	Input	Connect to VDD
INTP0			Connect to VDD or Vss
INTP1, INTP2	2-A	Input	Connect to VDD
AVDD1, AVDD2	_	-	Connect to VDD
AVREF, AVSS1, AVSS2			Connect to Vss
RESET	2	-	-
XT1	_	-	Connect to Vss
XT2			Open
IC			Directly connect to Vss

Remark ENDRUM : bit 2 of amplifier control register (AMPC)

SELPGSEPA: bit 2 of amplifier mode register 0 (AMPM0)

ENCAP : bit 3 of amplifier control register (AMPC)

ENCSYN : bit 5 of amplifier control register (AMPC)

ENREEL : bit 6 of amplifier control register (AMPC)

ENCTL : bit 1 of amplifier control register (AMPC)

ENCOMP : bit 4 of amplifier control register (AMPC)



Figure 2-1. I/O Circuits of Respective Pins (1/2)

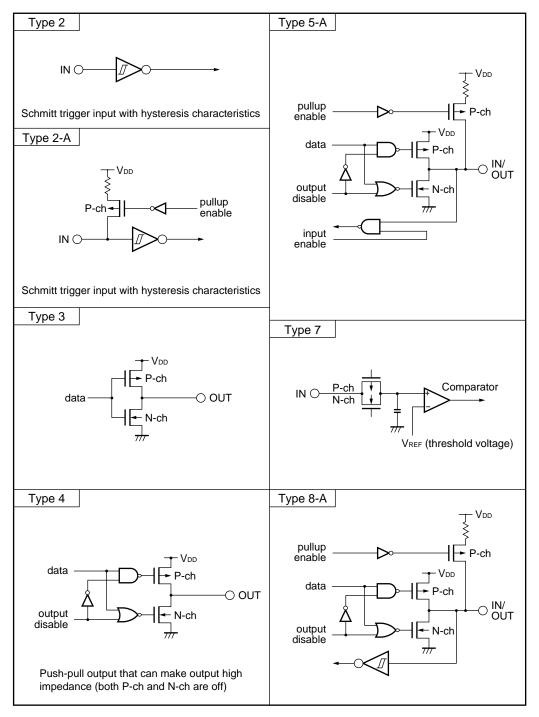
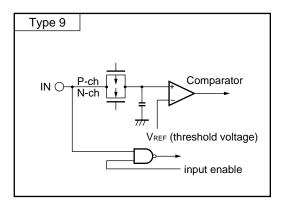


Figure 2-1. I/O Circuits of Respective Pins (2/2)





3. INTERNAL BLOCK FUNCTION

3.1 CPU REGISTERS

3.1.1 General-Purpose Registers

The μ PD784915 has eight banks of general-purpose registers. One bank consists of sixteen 8-bit general-purpose registers. Two of these 8-bit registers can be used in pairs as a 16-bit register. Four of the 16-bit general-purpose registers can be used to specify a 24-bit address in combination with an 8-bit address expansion register.

These eight banks of general-purpose registers can be selected by software or context switching function.

The general-purpose registers, except for the address expansion registers V, U, T, and W, are mapped to the internal RAM.

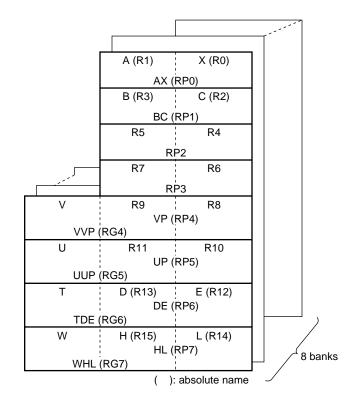


Figure 3-1. Configuration of General-Purpose Register

Caution Although R4, R5, R6, R7, RP2, and RP3 can be used as X, A, C, B, AX, and BC registers, respectively, by setting the RSS bit of PSW to 1, do not use this function. The function of the RSS bit is planned to be deleted from the future models in the 78K/IV Series.



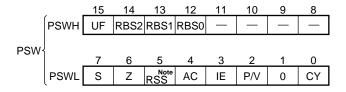
3.1.2 Other CPU Registers

(1) Program counter

The program counter of the μ PD784915 is 20 bits wide. The value of the program counter is automatically updated as the program is executed.

(2) Program status word

This is a register that holds the various statuses of the CPU. Its contents are automatically updated as the program is executed.



Note The RSS flag is provided to maintain compatibility with the microcomputers in the 78K/III Series. Always clear this flag to 0 except when the software of the 78K/III Series is used.

(3) Stack pointer

This is a 24-bit pointer that holds the first address of the stack.

Be sure to write 0 to the higher 4 bits.

3.2 MEMORY SPACE

The $\mu PD784915$ can access a 64K-byte memory space.

The addresses of the internal ROM and internal data areas are as follows:

Internal ROM area: 0000H-BFFFHInternal data area: FA00H-FFFFH

Caution Some products in the 78K/IV Series can access up to 1M bytes of memory space in an address expansion mode which is set by the LOCATION instruction. However, the memory space of the μ PD784915 is 64K bytes (0000H through FFFFH). Therefore, be sure to execute the LOCATION 0 instruction immediately after reset to set the memory space to 64K bytes (the LOCATION instruction cannot be used more than once).

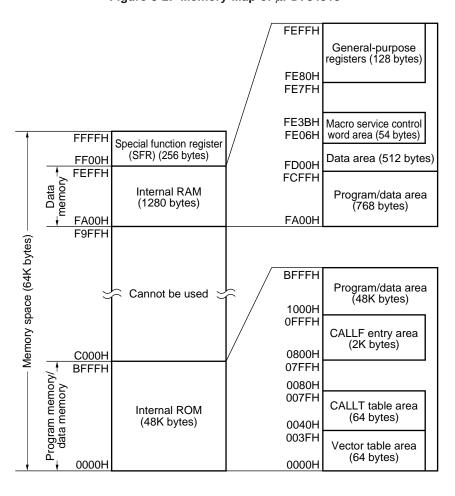


Figure 3-2. Memory Map of μ PD784915



3.3 SPECIAL FUNCTION REGISTERS (SFRs)

Special function registers are assigned special functions and mapped to a 256-byte space of addresses FF00H through FFFFH. These registers include mode registers and control registers that control the internal peripheral hardware units.

Caution Do not access an address to which no SFR is assigned. If such an address is accessed by mistake, the μ PD784915 may be deadlocked. This deadlock can be cleared only by reset input.

Table 3-1. lists the special function registers (SFRs). The meanings of the symbols in this table area as follows:

Abbreviation	Abbreviation of an S	SFR. This	abbreviation is	s reserved for	NEC's assembler
	(RA78K4). With a C	compiler (0	CC78K4), the a	abbreviation car	n be used as a bit-
	type sfr variable by t	the #pragm	a sfr instructio	n.	

R/W: Read/write : Read only : Write only

• Bit length Indicates the bit length (word length) of the SFR.

• Bit units for manipulation Indicates bit units in which the SFR in question can be manipulated. An SFR that can be manipulated in 16-bit units can be described as the operand sfrp of an instruction. Specify an even address to manipulate this SFR.

> An SFR that can be manipulated in 1-bit units can be described for a bit manipulation instruction.



Table 3-1. Special Function Registers (1/4)

Addraga	Chariel Function Devictor (CFD) Name	Cumbal	DAM	Bit		it Units f		After
Address	Special Function Register (SFR) Name	Symbol	R/W	Length	1 bit	anipulati 8 bits	16 bits	Releasing Reset
FF00H	Port 0	P0	R/W	8	0	Obits	-	Undefined
FF04H	Port 4	P4	-	8	0	0	_	Ondomica
FF05H	Port 5	P5		8	0	0	_	
FF06H	Port 6	P6		8	0	0	_	
FF07H	Port 7	P7	R	8	0	0	_	
FF08H	Port 8	P8	R/W	8	0	0	_	
FF09H	Port 9	P9		8	0	0	_	
FF0EH	Port 0 buffer register L	P0L	1	8	0	0	_	
FF0FH	Port 0 buffer register H	P0H		8	0	0	_	
FF10H	Timer 0 compare register 0	CR00	1	16	_	_	0	Cleared to 0
FF11H	Event counter compare register 0	ECC0	W	8	_	0	_	
FF12H	Timer 0 compare register 1	CR01	R/W	16	_	_	0	
FF13H	Event counter compare register 1	ECC1	W	8	_	0	_	
FF14H	Timer 0 compare register 2	CR02	R/W	16	_	_	0	
FF15H	Event counter compare register 2	ECC2	W	8	_	0	_	
FF16H	Timer 1 compare register 0	CR10	R/W	16	_	_	0	
FF17H	Event counter compare register 3	ECC3	W	8	_	0	_	
FF18H	Timer 1 compare register 1	CR11	R/W	16	_	_	0	
FF1AH	Timer 1 compare register 2	CR12	R	16	_	_	0	
FF1CH	Timer 1 compare register 3	CR13	R/W	16	_	_	0	
FF1EH	Timer 2 compare register 0	CR20		16	-	-	0	
FF20H	Port 0 mode register	PM0	W	8	-	0	_	FFH
FF24H	Port 4 mode register	PM4		8	-	0	_	
FF25H	Port 5 mode register	PM5		8	-	0	_	
FF26H	Port 6 mode register	PM6		8	-	0	_	
FF28H	Port 8 mode register	PM8		8	-	0	_	FDH
FF29H	Port 9 mode register	PM9		8	-	0	-	7FH
FF2EH	Real-time output port 0 control register	RTPC	R/W	8	0	0	_	00H
FF30H	Timer register 0	TM0	R	16	-	-	0	Cleared to 0
FF31H	Event counter	EC	R/W	8	-	0	_	
FF32H	Timer register 1	TM1	R	16	_	_	0	
FF34H	Free running counter (bits 0-15)	FRCL		16	-	-	0	0000H
FF35H	Free running counter (bits 16-21)	FRCH		8	-	0	_	00H
FF36H	Timer register 2	TM2		16	-	_	0	Cleared to 0
FF38H	Timer control register 0	TMC0	R/W	8	0	0	-	00H
FF39H	Timer control register 1	TMC1		8	0	0	-	
FF3AH	Timer control register 2	TMC2		8	0	0	-	
FF3BH	Timer control register 3	TMC3		8	0	0	_	00×00000

Remark Cleared to 0: Counter is initialized to 0 within 16 clocks after the RESET signal has been deasserted (the contents before initialization are undefined).



Table 3-1. Special Function Registers (2/4)

			Bit		В	it Units f	or	After	
Address	Special Function Register (SFR) Name	Symbol	R/W	Length	Manipulation			Releasing	
					1 bit	8 bits	16 bits	Reset	
FF3CH	Timer register 3	TM3	R	16	-	-	0	Cleared to 0	
FF3DH	Timer control register 4	TMC4	R/W	8	0	0	-	××000000	
FF3EH	Timer register 4	TM4	R	16	-	-	0	Cleared to 0	
FF48H	Port 8 mode control register	PMC8	R/W	8	0	0	_	00H	
FF4DH	Trigger source select register	TRGS0		8	0	0	_		
FF4EH	Pull-up resistor option register L	PUOL		8	0	0	_		
FF4FH	Pull-up resistor option register H	PUOH		8	0	0	-		
FF50H	Input control register	ICR		8	0	0	_	10H	
FF51H	Up/down counter count register	UDC		8	-	0	_	Undefined	
FF52H	Event divider counter	EDV	R	8	-	0	_	Cleared to 0	
FF53H	Capture mode register	CPTM	R/W	8	0	0	_	00H	
FF54H	Timer register 5	TM5	R	16	-	-	0	Cleared to 0	
FF56H	Timer 3 capture register 0	CPT30		16	-	-	0		
FF58H	Timer 0 output mode register	TOM0	W	8	-	0	_	××000000	
FF59H	Timer 0 output control register	TOC0		8	-	0	_	00H	
FF5AH	Timer 1 output mode register	TOM1Note 1	R/W	8	-	0	_	80H	
FF5BH	Timer 1 output control register	TOC1	W	8	-	0	-	00H	
FF5CH	Timer 3 compare register 0	CR30	R/W	16	-	_	0	Cleared to 0	
FF5EH	Timer 3 compare register 1	CR31		16	ı	-	0		
FF60H	Port 8 buffer register L	P8L		8	0	0	_	000×0×0×	
FF63H	Up/down counter compare register	UDCC	W	8	-	0	_	Undefined	
FF65H	Trigger source select register 1	TRGS1	R/W	8	0	0	_	00H	
FF66H	Port 6 mode control register	PMC6		8	0	0	_		
FF68H	A/D converter mode register	ADM		16	ı	-	0	0000H	
		ADMLNote 2		8	0	0	_		
FF6AH	A/D conversion result register	ADCR	R	8	-	0	_	Undefined	
FF6CH	Hardware watch counter 0	HW0	R/W	16	-	-	0	Not affected	
FF6EH	Hardware watch counter 1	HW1	R	16	-	-	O by reset		
FF6FH	Watch mode register	WM	R/W	8	0	0	_	00××0×00	
FF70H	PWM control register 0	PWMC0	R/W	8	0	0	-	05H	
FF71H	PWM control register 1	PWMC1		8	0	0	-	15H	
FF72H	PWM0 modulo register	PWM0		16	-	_	0	0000H	
FF73H	PWM2 modulo register	PWM2		8	1	0	-	00H	
FF74H	PWM1 modulo register	PWM1		16	-	_	0	0000H	
FF75H	PWM3 modulo register	PWM3		8	-	0	_	00H	

Notes 1. When the TOM1 register is read, the write sequence of the REC driver is read (bits 0 and 1).

2. ADML is the lower 8 bits of ADM and can be manipulated in 1- or 8-bit units.

Remark Cleared to 0: Counter is initialized to 0 within 16 clocks after the reset signal has been deasserted (the contents before initialization are undefined).



Table 3-1. Special Function Registers (3/4)

					Bit	В	it Units f	or	After
Address	Special Function Register (SFR) Name		Symbol		Length	Manipulation		on	Releasing
						1 bit	8 bits	16 bits	Reset
FF76H	PWM5 modulo register	PW	M5	R/W	16	-	-	0	0000H
FF77H	PWM4 modulo register	PW	M4		8	-	0	-	00H
FF78H	Event divider control register	ED	VC	W	8	-	0	-	K00H
FF79H	Clock output mode register	CLC	MC	R/W	8	0	0	-	00H
FF7AH	Timer 4 capture/compare register 0	CR	40		16	-	-	0	Cleared to 0
FF7BH	Clock control register	C	С		8	0	0	-	00H
FF7CH	Timer 4 capture register 1	CR	41	R	16	-	-	0	Cleared to 0
FF7DH	Capture/compare control register	CR	C	W	8	-	0	-	00H
FF7EH	Timer 5 compare register	CR	50	R/W	16	-	-	0	Cleared to 0
FF84H	Serial mode register 1	CSI	M1		8	0	0	-	00H
FF85H	Serial shift register 1	SIC	D1		8	-	0	-	Undefined
FF88H	Serial mode register 2	CSI	M2		8	0	0	-	00H
FF89H	Serial shift register 2	SIC)2		8	-	0	-	Undefined
FF8AH	Serial control register 2	CSI	C2		8	-	0	-	00H
FF91H	Head amplifier switch output control register	HA	PC		8	0	0	-	
FF94H	Amplifier control register	AM	PC		8	0	0	-	
FF95H	Amplifier mode register 0	AMF	PM0		8	0	0	-	
FF96H	Amplifier mode register 1	AMPM1			8	0	0	-	
FF97H	Gain control register	CTLM			8	0	0	-	
FFA0H	External interrupt mode register	INTM0			8	0	0	-	000000×0
FFA1H	External capture mode register 1	INT	M1		8	0	0	-	00H
FFA2H	External capture mode register 2	INT	M2		8	0	0	-	
FFA6H	Key interrupt control register	KE'	YC		8	0	0	-	70H
FFA8H	In-service priority register	ISF	PR	R	8	0	0	-	00H
FFAAH	Interrupt mode control register	IM	С	R/W	8	0	0	-	80H
FFACH	Interrupt mask flag register	MK0L	MK0		8	0	0	0	FFH
FFADH		MK0H	IVINO		8	0	0		
FFAEH		MK1L	MK1		8	0	0	0	
FFAFH		MK1H	IVIIXI		8	0	0		
FFB0H	FRC capture register 0L	CPT0L		R	16	ı	_	0	Cleared to 0
FFB1H	FRC capture register 0H	СРТ0Н			8	-	0	_	
FFB2H	FRC capture register 1L	CPT1L			16	ı	_	0	
FFB3H	FRC capture register 1H	CPT1H			8	-	0	-	
FFB4H	FRC capture register 2L	CPT2L			16	-	-	0	
FFB5H	FRC capture register 2H	CPT2H			8	-	0	-	
FFB6H	FRC capture register 3L	CPT3L			16	-	-	0	
FFB7H	FRC capture register 3H	СРТЗН			8	-	0	-	
FFB8H	FRC capture register 4L	CP1	T4L		16	-	-	0	

Remark Cleared to 0: Counter is initialized to 0 within 16 clocks after the reset signal has been deasserted (the contents before initialization are undefined).



Table 3-1. Special Function Registers (4/4)

				Bit	Bit Units for		or	After
Address	Special Function Register (SFR) Name	Symbol	R/W	Length	M	anipulati	on	Releasing
					1 bit	8 bits	16 bits	Reset
FFB9H	FRC capture register 4H	CPT4H	R	8	-	0	-	Cleared to 0
FFBAH	FRC capture register 5L	CPT5L		16	-	-	0	
FFBBH	FRC capture register 5H	CPT5H		8	-	0	-	
FFC0H	Standby control register	STBC	R/W	8	ı	0	-	0000×000
FFC4H	Execution speed select register	MM	W	8	-	0	-	20H
FFCEH	CPU clock status register	PCS	R	8	0	0	-	00H
FFCFH	Oscillation stabilization time specification register	OSTS	W	8	-	0	-	
FFE0H	Interrupt control register (INTP0)	PIC0	R/W	8	0	0	_	43H
FFE1H	Interrupt control register (INTCPT3)	CPTIC3		8	0	0	-	
FFE2H	Interrupt control register (INTCPT2)	CPTIC2		8	0	0	-	
FFE3H	Interrupt control register (INTCR00)	CRIC12		8	0	0	-	
FFE4H	Interrupt control register (INTCR00)	CRIC00		8	0	0	-	
FFE5H	Interrupt control register (INTCLR1)	CLRIC1		8	0	0	_	
FFE6H	Interrupt control register (INTCR10)	CRIC10		8	0	0	-	
FFE7H	Interrupt control register (INTCR01)	CRIC01		8	0	0	-	
FFE8H	Interrupt control register (INTCR02)	CRIC02		8	0	0	-	
FFE9H	Interrupt control register (INTCR11)	CRIC11		8	0	0	-	
FFEAH	Interrupt control register (INTCPT1)	CPTIC1		8	0	0	_	
FFEBH	Interrupt control register (INTCR20)	CRIC20		8	0	0	_	
FFEDH	Interrupt control register (INTTB)	TBIC		8	0	0	-	
FFEEH	Interrupt control register (INTAD)	ADIC		8	0	0	_	
FFEFH	Interrupt control register (INTP2)Note	PIC2		8	0	0	_	
	Interrupt control register (INTCR40)Note	CRIC40						
FFF0H	Interrupt control register (INTUDC)	UDCIC		8	0	0	-	
FFF1H	Interrupt control register (INTCR30)	CRIC30		8	0	0	-	
FFF2H	Interrupt control register (INTCR50)	CRIC50		8	0	0	-	
FFF3H	Interrupt control register (INTCR13)	CRIC13		8 🔾		0	-	
FFF4H	Interrupt control register (INTCSI1)	CSIIC1		8 0 0 -		-		
FFF5H	Interrupt control register (INTW)	WIC		8	0 0 -			
FFF7H	Interrupt control register (INTP1)	PIC1		8	0 0 -			
FFF8H	Interrupt control register (INTP3)	PIC3		8	0	0	-	
FFFAH	Interrupt control register (INTCSI2)	CSIIC2		8	0	0	-	

Note PIC2 and CRIC40 are at the same address (register).

Remark Cleared to 0: Counter is initialized to 0 within 16 clocks after the reset signal has been deasserted (the contents before initialization are undefined).

3.4 PORTS

The μ PD784915 is provided with the ports shown in Figure 3-3. Table 3-2 shows the function of each port.

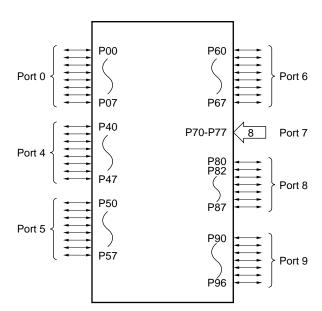


Figure 3-3. Port Configuration

Table 3-2. Port Function

Name	Pin Name	Function	Specification of Pull-up Resistor
Port 0	P00-P07	Can be set in input or output mode in	Pull-up resistors are connected to all
Port 4	P40-P47	1-bit units.	pins in input mode.
Port 5	P50-P57		
Port 6	P60-P67		
Port 7	P70-P77	Input port	Pull-up resistor is not provided.
Port 8	P80, P82-P87	Can be set in input or output mode in	Pull-up resistors are connected to all
Port 9	P90-P96	1-bit units.	pins in input mode.



3.5 REAL-TIME OUTPUT PORT

A real-time output port consists of a port output latch and a buffer register (refer to Figure 3-4).

The function to transfer the data prepared in advance in the buffer register to the output latch when a trigger such as a timer interrupt occurs, and output the data to an external device is called a real-time output function. A port used in this way is called a real-time output port (RTP).

Table 3-3. shows the real-time output ports of the μ PD784915.

Table 3-4. shows the trigger sources of RTPs.

Figure 3-4. Configuration of RTP

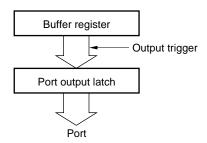


Table 3-3. Bit Configuration of RTP

		Number of Bits of	Number of Bits That	
RTP	Shared with:	Real-Time Output	Can Be Specified as	Remark
		Data	RTP	
RTP0	Port 0	4 bits x 2 channels or	4-bit units	-
		8 bits x 1 channel		
RTP8	Port 8	1 bit x 1 channel and	1-bit units	Pseudo Vsync output: 1 channel (RTP80)
		2 bits x 1 channel		Head amplifier switch: 1 channel (RTP82)
				Chrominance rotation signal output: 1
				channel (RTP83)

Table 3-4. Trigger Sources of RTP

	Trigger Source	INTCR00	INTCR01	INTCR02	INTCR13	INTCR50	INTCR0	Remark
RTP								
RTP0	Higher 4 bits		0					
	Lower 4 bits			0			0	
	All 8 bits			0			0	
RTP8	Bit 0		0	0	0	0		Note 1
	Bits 2 and 3	0						Note 2

 $\textbf{Notes 1.} \ \ \textbf{Select one of the four trigger sources}.$

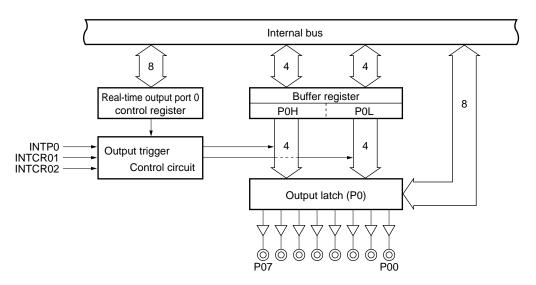
2. When the real-time output port mode is set by the port mode control register 8 (PMC8), the HASW and ROT-C signals that are set by the head amplifier switch output control register (HAPC) are directly output. The HASW and ROT-C signals are synchronized with HSW output (TM0-CR00 coincidence signal). However, the set signal is output immediately when the HAPC register is rewritten.



Figures 3-5. and 3-6. show the block diagrams of RTP0 and RTP8.

Figure 3-7. shows the types of RTP output trigger sources.

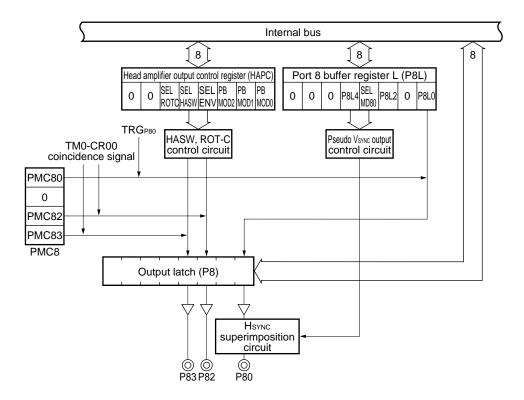
Figure 3-5. Block Diagram of RTP0



Remark INTCR01: TM0-CR01 coincidence signal

INTCR02: TM0-CR02 coincidence signal

Figure 3-6. Block Diagram of RTP8





Real-time output port 0 control register (RTPC) INTP0 🔘 TM0 Selector Trigger of P0H Trigger of P0L CR00 Interrupt and timer output CR01 ► Trigger of P82 and P83 CR02 Selector Trigger of P80 TM1 Trigger source select register 0 (TRGS0) CR10 Interrupt and timer output CR11 Capture CR12 Interrupt CR13 TM5 CR50 ► Interrupt

Figure 3-7. Types of RTP Output Trigger Sources



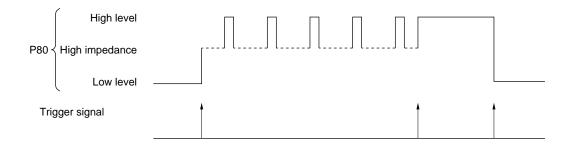
RTP80 can output low-level, high-level, and high-impedance values real-time.

Because RTP80 can superimpose a horizontal sync signal, it can be used to create pseudo vertical sync signal. When RTP80 is set in the pseudo Vsync output mode, it repeatedly outputs a specific pattern when an output trigger occurs.

Figure 3-8. shows the operation timing of RTP80.

Figure 3-8. Example of Operation Timing of RTP80

(a) When Hsync signal is superimposed



(b) Pseudo Vsync output mode





3.6 SUPER TIMER UNIT

The μ PD784915 is provided with a super timer unit that consists of the timers shown in Table 3-5.

Table 3-5. Configuration of Super Timer Unit

Unit Name	Timer/Counter	Resolution	Maximum Count Time	Register	Remark
Timer 0	TM0	1 <i>μ</i> s	65.5 ms	CR00	Controls delay of video head switching signal
	(16-bit timer)			CR01	Controls delay of audio head switching signal
				CR02	Controls pseudo VsyNc output timing
	EC	_	_	ECC0, ECC1,	Creates internal head switching signal
	(8-bit counter)			ECC2, ECC3	
Free running	FRC	125 ns	524 ms	CPT0	Detects reference phase (to control drum phase)
counter	(22-bit counter)			CPT1	Detects phase of drum motor (to control drum phase)
				CPT2	Detects speed of drum motor (to control drum speed)
				СРТ3	Detects speed of capstan motor (to control speed of capstan motor)
				CPT4, CPT5	Detects remaining tape for reel FG
Timer 1	TM1 (16-bit timer)	1 μs	65.5 ms	CR10	Playback: Creates internal reference signal Recording: Buffer oscillator in case Vsync is missing
				CR11	Controls RECCTL output timing
				CR12	Detects phase of capstan motor (to control capstan phase)
				CR13	Controls V _{SYNC} mask as noise preventive measures
	TM3 (16-bit timer)	1 μs or 1.1 μs	65.5 ms or 71.5 ms	CR30, CR31	Controls duty detection timing of PBCTL signal
				CPT30	Measures cycle of PBCTL signal
	EDV (8-bit counter)	-	_	EDVC	Divides CFG signal frequency
Timer 2	TM2 (16-bit timer)	1 μs	65.5 ms	CR20	Can be used as interval timer (to control system)
Timer 4	TM4 (16-bit timer)	2 μs	131 ms	CR40	Detects duty of remote controller signal (to decode remote controller signal)
				CR41	Measures cycle of remote controller signal (to decode remote controller signal)
Timer 5	TM5	2 μs	131 ms	CR50	Can be used as interval timer (to control sys-
	(16-bit timer)				tem)
Up/down	UDC	_	-	UDCC	Creates linear tape counter
counter	(5-bit counter)				
PWM output		_	_	PWM0, PWM1,	16-bit resolution (carrier frequency: 62.5 kHz)
unit				PWM5	
				PWM2, PWM3,	8-bit resolution (carrier frequency: 62.5 kHz)
				PWM4	

(1) Timer 0 unit

Timer 0 unit creates head switching signal and pseudo VsyNc output timing from the PG and FG signals of the drum motor.

This unit consists of an event counter (EC: 8 bits), four compare registers (ECC0 through ECC3), a timer (TM0: 16 bits), and three compare registers (CR00 through CR02).

A signal indicating coincidence between the value of timer 0 and the value of a compare register can be used as the output trigger of the real-time output port.

(2) Free running counter unit

The free running counter unit detects the speed and phase of the drum motor, and the speed and reel speed of the capstan motor.

This unit consists of a free running counter (FRC), six capture registers (CPT0 through CPT5), a VsyNc separation circuit, and a HsyNc separation circuit.

(3) Timer 1 unit

Timer 1 unit is a reference timer unit synchronized with the frame cycle and creates the RECCTL signal, detects the phase of the capstan motor, and detects the duty factor of the PBCTL signal. This unit consists of the following three groups:

- Timer 1 (TM1), compare registers (CR10, CR11, and CR13), and capture register (CR12)
- Timer 3 (TM3), compare registers (CR30 and CR31), and capture register (CPT30)
- Event divider counter (EDV) and compare register (EDVC)

The TM1-CR13 coincidence signal can be used for automatic unmasking of Vsync or as the output trigger of the real-time output port.

ZEC

Selector DPGIN ©-Selector Divider Mask Selector Clear Output control circuit Writes — TM0 -(INTCR00) CR00 → RTP Clear Output control circuit DFGIN © EC -RTP, A/D (INTCR01) CR01 - Output control circuit CR02 → PTO02 ECC3 F/F ECC2 -(INTCR02) -RTP ECC1 (Superimposition) (Superimposition) ECC0 Analog circuit Hsync separation → To P80 circuit V_{SYNC} separation Selector Selector circuit -(INTCLR1) CSYNCIN @-FRC Selector Ţ CPT0 Capture Capture Mask REELOIN ©-CPT1 (INTCPT1) CPT2 (INTCPT2) Capture CPT3 (INTCPT3) Capture CPT4 Capture REEL1IN ◎-CPT5 Capture Selector INTP3 Clear 1 EDVC Output control circuit - PTO10 CFGIN ◎ Clear Selector -(INTCR10) TM1 ₹ CR10 - PTO11 Output control circuit CR11 **PBCTL** -(INTCR11) Selector Clear PTO10 CR12 (INTCR12) Capture TM3 (INTCR13) CR13 PTO11 To PBCTL signal input block CR31 **FFLVL** Capture CPT30 CTL F/F

Figure 3-9. Block Diagram of Super Timer Unit (TM0, FRC, TM1) ★

NEC μ PD784915

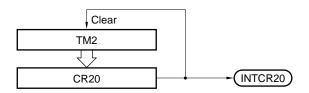
(4) Timer 2 unit

Timer 2 unit is a general-purpose 16-bit timer unit.

This unit consists of a timer (TM2) and a compare register (CR20).

The timer is cleared when the TM2-CR20 coincidence signal occurs, and at the same time, an interrupt is generated.

Figure 3-10. Block Diagram of Timer 2 Unit



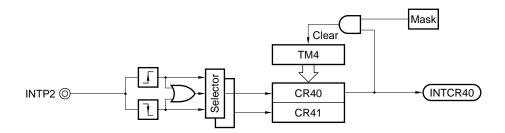
(5) Timer 4 unit

Timer 4 unit is a general-purpose 16-bit timer unit.

This unit consists of a timer (TM4), a capture/compare register (CR40), and a capture register (CR41).

The value of the timer is captured to CR40/CR41 when the INTP2 signal is input. This timer can be used to decode a remote controller signal.

Figure 3-11. Block Diagram of Timer 4 Unit



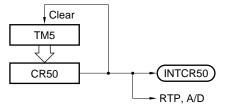
(6) Timer 5 unit

Timer 5 unit is a general-purpose 16-bit timer unit.

This unit consists of a timer (TM5) and a compare register (CR50).

The timer is cleared by the TM5-CR50 coincidence signal, and at the same time, an interrupt is generated.

Figure 3-12. Block Diagram of Timer 5 Unit





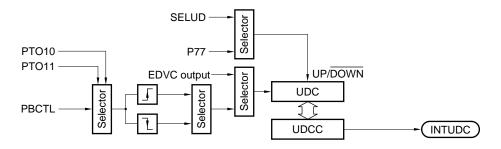
(7) Up/down counter unit

The up/down counter unit is a counter that realizes a linear time counter.

This unit consists of an up/down counter (UDC) and a compare register (UDCC).

The up/down counter counts up the rising edges of PBCTL and counts down the falling edges of PBCTL. When the value of the up/down counter coincides with the value of the compare register, or when the counter underflows, an interrupt is generated.

Figure 3-13. Block Diagram of Up/Down Counter Unit



(8) PWM output unit

The PWM output unit has three 16-bit accuracy output lines (PWM0, PWM1, and PWM5) and 8-bit accuracy output lines (PWM2 through PWM4). The carrier frequency of all the output lines is 62.5 kHz (fclk = 8 MHz). PWM0 and PWM1 can be used to control the drum motor and capstan motor.

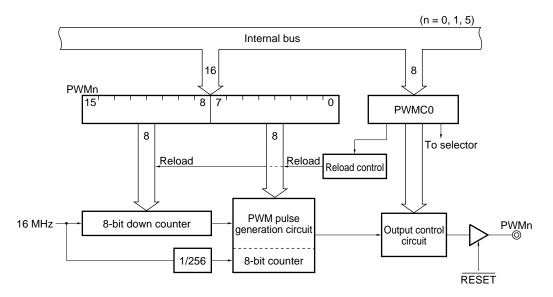


Figure 3-14. Block Diagram of 16-Bit PWM Output Unit



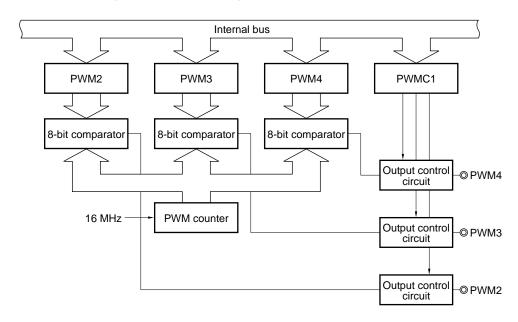


Figure 3-15. Block Diagram of 8-Bit PWM Output Unit

3.7 SERIAL INTERFACE

The $\mu PD784915$ is provided with the serial interfaces shown in Table 3-6.

Data can be automatically transmitted or received through these serial interfaces, when the macro service is used.

Table 3-6. Types of Serial Interfaces

Name	Function
Serial interface channel 1	Clocked serial interface (3-line)
	Bit length: 8 bits
	Clock rate: External clock/31.25 kHz/62.5 kHz/125 kHz/250 kHz/500 kHz/1 MHz
	(fclk = 8 MHz)
	MSB first/LSB first selectable
Serial interface channel 2	Clocked serial interface (3-line)
	Bit length: 8 bits
	Clock rate: External clock/31.25 kHz/62.5 kHz/125 kHz/250 kHz/500 kHz/1 MHz
	(fclk = 8 MHz)
	MSB first/LSB first selectable
	BUSY/STRB control function



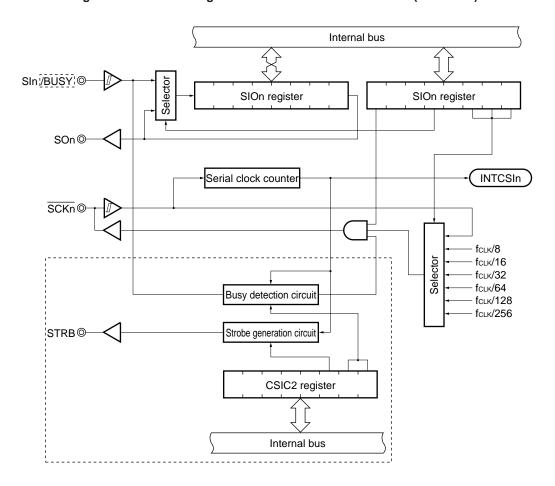


Figure 3-16. Block Diagram of Serial Interface Channel n (n = 1 or 2)

Remark The circuits enclosed in the broken line are provided to serial interface channel 2 only.

3.8 A/D CONVERTER

The μ PD784915 has an analog-to-digital (A/D) converter with 12 multiplexed analog inputs (ANI0 through ANI11). This A/D converter is of successive approximation type, and the conversion result is held by an 8-bit A/D conversion result register (ADCR) (conversion time: 10 μ s at fclk = 8 MHz).

A/D conversion can be started in the following two modes:

- Hardware start: Conversion is started by a hardware trigger Note.
- Software start: Conversion is started by setting a bit of the A/D conversion mode register (ADM).

After conversion has been started, the A/D converter operates in the following modes:

- Scan mode: Sequentially selects more than one analog input to obtain data to be converted from all the pins.
- Select mode: Use only one pin for analog input to obtain successive data.

When the conversion result is transferred to ADCR, interrupt request INTAD is generated. By processing this interrupt with the macro service, the conversion result can be successively transferred to memory.

A mode in which starting A/D conversion of the next pin is kept pending until the value of ADCR is read is also available. When this ode is used, reading the conversion result by mistake when timing is shifted because an interrupt is disabled can be prevented.

Note A hardware trigger is the following coincidence signals, one of which is selected by the trigger source select register 1 (TRGS1):

- TM0-CR01 coincidence signal
- TM0-CR02 coincidence signal
- TM1-CR13 coincidence signal
- TM5-CR50 coincidence signal



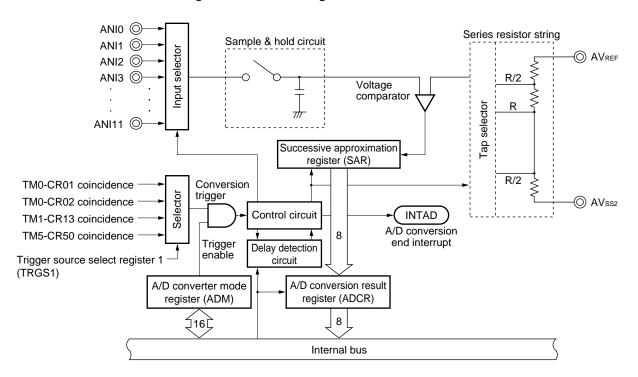


Figure 3-17. Block Diagram of A/D Converter

3.9 VCR ANALOG CIRCUITS

The μ PD784915 is provided with the following VCR analog circuits:

- CTL amplifier
- RECCTL driver (rewritable)
- DPG comparator
- DFG amplifier
- DPFG separation circuit (ternary separation circuit)
- CFG amplifier
- Reel FG comparator (2 channels)
- CSYNC comparator



(1) CTL amplifier/RECCTL driver

The CTL amplifier is used to amplify the playback control (PBCTL) signal that is reproduced from the CTL signal recorded on a VCR tape.

The gain of the CTL amplifier is set by the gain control register (CTLM). Thirty-two types of gains can be set in increments of about 1.78 dB.

The μ PD784195 is also provided with a gain control signal generation circuit that monitors the status of the amplifier output to perform optimum gain control by program. The gain control signal generation circuit generates a CTL detection flag that identifies the amplitude status of the CTL amplifier output. By using this CTL detection flag, the gain of the CTL amplifier can be optimized.

The RECCTL driver writes a control signal onto a VCR tape.

This driver operates in two modes: REC mode that is used for recording, and rewrite mode used to rewrite the VISS signal. The output status of the RECCTL± pin is changed by hardware, by using the timer output from the super timer unit as a trigger.

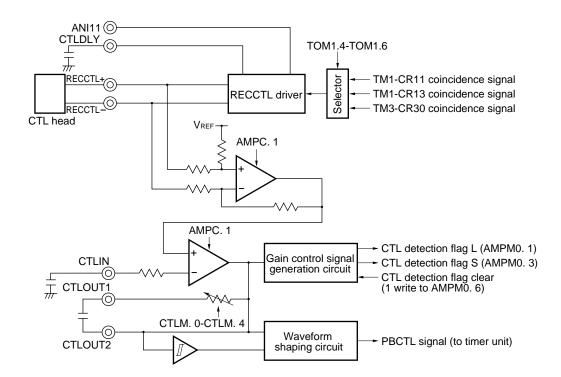


Figure 3-18. Block Diagram of CTL Amplifier and RECCTL Driver

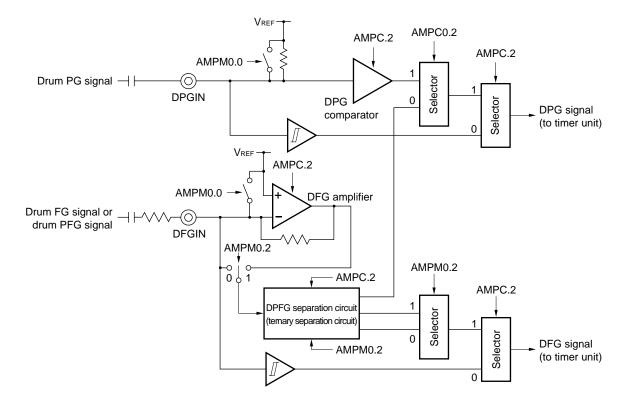


(2) DPG comparator, DFG amplifier, and DFPG separation circuit

The DPG comparator converts the drum PG (DPG) signal that indicates the phase information of the drum motor into a logic signal.

The DFG amplifier amplifies the drum FG (DFG) signal that indicates the speed information of the drum motor. The DPFG separation circuit (ternary separation circuit) separates a drum PFG (DPFG) signal having speed and phase information into a DFG and DPG signals.

Figure 3-19. Block Diagram of DPG Comparator, DFG Amplifier, and DPFG Separation Circuit



(3) CFG amplifier

The CFG amplifier amplifies the capstan FG (CFG) signal that indicates the speed information of the capstan motor. This amplifier consists of an operational amplifier and a comparator. The gain of the operational amplifier is set by using an external resistor.

When the gain of the operational amplifier is set to 50 dB, the output duty accuracy of the CFG signal can be improved to $50.0 \pm 0.3\%$.

Capstan FG signal — CFGIN

CFGAMPO

AMPMO.0

CFGCPIN

CFG amplifier

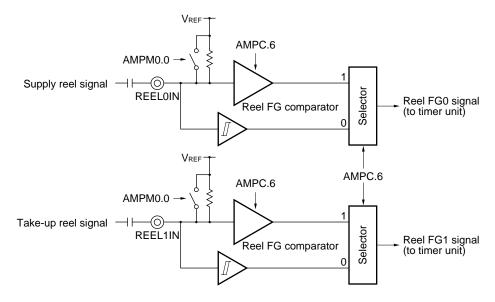
Figure 3-20. Block Diagram of CFG Amplifier



(4) Reel FG comparators

The reel FG comparator converts a reel FG signal that indicates the speed information of the reel motor into a logic signal. Two comparators, one for take-up and the other for supply, are provided.

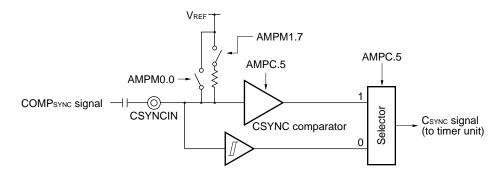
Figure 3-21. Block Diagram of Reel FG Comparators



(5) CSYNC comparator

The CSYNC comparator converts the COMPSYNC signal into a logic signal.

Figure 3-22. Block Diagram of COMPSYNC Comparator



NEC μ PD784915

(6) Reference amplifier

The reference amplifier generates a reference voltage (VREF) to be supplied to the internal amplifiers and comparators of the μ PD784915.

VREF (CFG amplifier)

VREF (CFG amplifier)

VREF (CFG amplifier)

ENCTL (AMPC.1)

VREF (CTL amplifier)

ENDRUM (AMPC.2)
ENREEL (AMPC.6)
ENCSYN (AMPC.5)

VREF (DFG amplifier, DPG comparator, reel FG comparator, and CSYNC comparator)

Figure 3-23. Block Diagram of Reference Amplifier

Remark Multiple reference amplifiers are provided to assure the accuracy of the amplifiers and comparators.



3.10 WATCH FUNCTION

The μ PD784915 has a watch function that counts the overflow signals of the watch timer by hardware. As the clock, the subsystem clock (32.768 kHz) is used.

Because this watch function is independent of the CPU, it can be used even while the CPU is in the standby mode (STOP mode) or is reset. In addition, this function can be used at a low voltage of $V_{DD} = 2.7 \text{ V (MIN.)}$.

Therefore, by using only the watch function with the CPU set in the standby mode or reset, a watch operation can be performed at a low voltage and low current dissipation.

In addition, the watch function can also be used while the CPU is in the normal operation mode, because a dedicated counter is provided.

The watch function can be used to count up to about 17 years of data.

The hardware watch counters (HW0 and HW1) are shared with external input counters. These counters execute counting at the falling edge of input to the P65 pin, and can be used to count the Hsync signals.

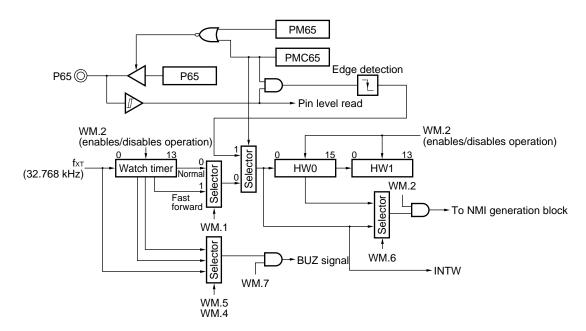


Figure 3-24. Block Diagram of Watch Counter

3.11 CLOCK OUTPUT FUNCTION

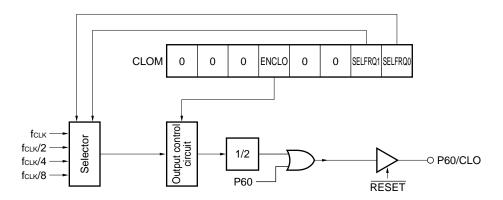
The μ PD784915 can output a square wave (with a duty factor of 50%) to the P60/CLO pin as the operating clock for the peripheral devices or other microcomputers. To enable or disable the clock output, and to set the frequency of the clock, the clock output mode register (CLOM) is used.

When setting the frequency, the division ratio can be set to fclk/n (where n = 2, 4, 8, or 16) (fclk = fosc/2: fosc is the oscillation frequency of the oscillator).

Figure 3-25. shows the configuration of the clock output circuit.

The clock output (CLO) pin is shared with P60.

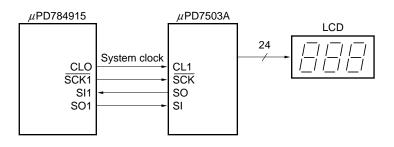
Figure 3-25. Block Diagram of Clock Output Circuit



Remark fclk: internal system clock

Caution Do not use the clock output function in the STOP mode. Clear ENCLO (CLOM.4) to 0 in the STOP mode.

Figure 3-26. Application Example of Clock Output Function





4. INTERNAL/EXTERNAL CONTROL FUNCTION

4.1 INTERRUPT FUNCTION

The μ PD784915 has as many as 30 interrupt sources, including internal and external sources. For 26 sources, a high-speed interrupt processing mode such as context switching or macro service can be specified by software. Table 4-1. lists the interrupt sources.

Table 4-1. Interrupt Sources

Interrupt			Interrupt Request Source	Interrupt	Macro	Context	Macro Service	Vector
Request	Priority	Name	Trigger	Control Reg-	Service	Switching	Control Word	Table
Туре		Ivaille	rrigger	ister Name	Service	Switching	Address	Address
Reset	-	RESET	RESET pin input	-	No	No	-	0000H
Non-	_	NMI	NMI pin input edge	_			-	0002H
maskable								
Maskable	0	INTP0	INTP0 pin input edge	PIC0	Yes	Yes	FE06H	0006H
	1	INTCPT3	EDVC output signal (CPT3 capture)	CPTIC3			FE08H	0008H
	2	INTCPT2	DFGIN pin input edge (CPT2 capture)	CPTIC2			FE0AH	000AH
	3	INTCR12	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	CRIC12			FE0CH	000CH
			capture)					
	4		TM0-CR00 coincidence signal	CRIC00			FE0EH	000EH
	5	INTCLR1	CSYNCIN pin input edge	CLRIC1			FE10H	0010H
	6	INTCR10		CRIC10			FE12H	0012H
	7	INTCR01	TM0-CR01 coincidence signal	CRIC01			FE14H	0014H
	8	INTCR02	TM0-CR02 coincidence signal	CRIC02			FE16H	0016H
	9	INTCR11	TM1-CR11 coincidence signal	CRIC11			FE18H	0018H
	10	INTCPT1	Pin input edge/EC output signal (CPT1 capture)	CPTIC1			FE1AH	001AH
	11	INTCR20	TM2-CR20 coincidence signal	CRIC20			FE1CH	001CH
	12	INTTB	Time base from FRC	TBIC			FE20H	0020H
	13	INTAD	A/D converter conversion end	ADIC			FE22H	0022H
	14	INTP2	INTP2 pin input edge	PIC2			FE24H	0024H
		INTCR40	TM4-CR40 coincidence signal	CRIC40				
	15	INTUDC	UDC-UDCC coincidence/UDC underflow	UDCIC			FE26H	0026H
	16	INTCR30	TM3-CR30 coincidence signal	CRIC30			FE28H	0028H
	17	INTCR50	TM5-CR50 coincidence signal	CRIC50			FE2AH	002AH
	18	INTCR13	TM1-CR13 coincidence signal	CRIC13			FE2CH	002CH
	19	INTCSI1	End of serial transfer (channel 1)	CSIIC1			FE2EH	002EH
	20	INTW	Overflow of watch timer	WIC			FE30H	0030H
	21	INTP1	INTP1 pin input edge	PIC1			FE34H	0034H
	22	INTP3	INTP3 pin input edge	PIC3			FE36H	0036H
	23	INTCSI2	End of serial transfer (channel 2)	CSIIC2			FE3AH	003AH
Operand error	-	-	Illegal operand of MOV STBC, #byte or LOCATION instruction	-	No	No	-	003CH
Software		_	Execution of BRK instruction	_			_	003EH
Contware		_	Execution of BRKCS instruction					UUSEN



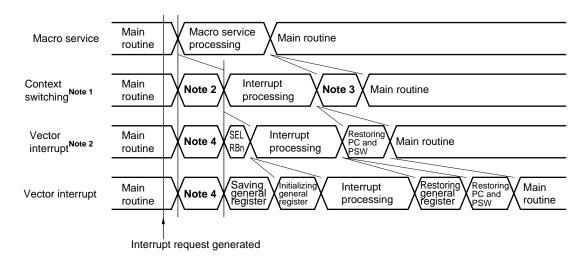


Figure 4-1. Differences in Operation Depending on Interrupt Processing Mode

- **Notes 1.** When the register bank switching function is used and when initial values are set in advance to the registers
 - 2. Selecting a register bank and saving PC and PSW by context switching
 - 3. Restoring register bank, PC, and PSW by context switching
 - 4. Saves PC and PSW to stack and loads vector address to PC



4.1.1 Vectored Interrupt

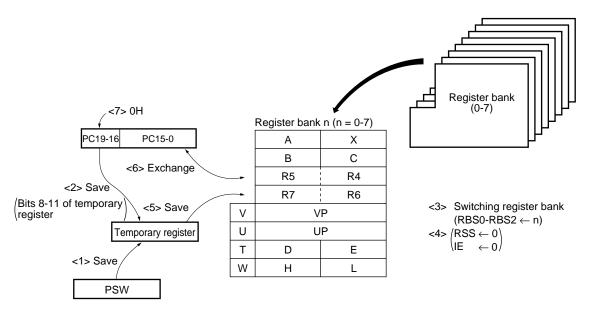
When an interrupt is acknowledged, an interrupt processing program is executed according to the data stored in the vector table area (the first address of the interrupt processing program created by the user).

Four levels of priorities can be specified by software for the vectored interrupts of the μ PD784915.

4.1.2 Context Switching

When an interrupt request is generated or when the BRKCS instruction is executed, a specific register bank is selected by hardware, and execution branches to a vector address set in advance in the register bank. At the same time, the current contents of the program counter (PC) and program status word (PSW) are saved to the registers in the register bank. Because the contents of PC and PSW are not saved to the stack area, execution can be branched to an interrupt processing routine more quickly than the vector interrupt.

Figure 4-2. Context Switching Operation When Interrupt Request Is Generated

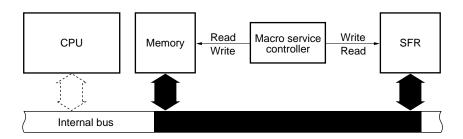




4.1.3 Macro Service

The macro service is a function to transfer data between the memory and a special function register (SFR) without intervention by the CPU. A macro service controller accesses the memory and SFR and directly transfers the data. Because the status of the CPU is not saved or restored, data can be transferred more quickly than context switching. The processing that can be executed with the macro service is described below.

Figure 4-3. Macro Service



(1) Counter mode

In this mode, the value of the macro service counter (MSC) is decremented when an interrupt occurs. This mode can be used to execute the division operation of an interrupt or count the number of times an interrupt has occurred.

When the value of the macro service counter has been decremented to 0, a vector interrupt occurs.



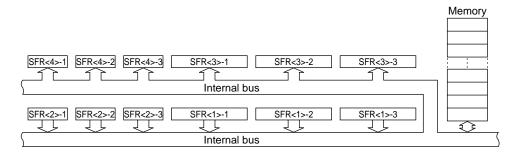
(2) Compound data transfer mode

When an interrupt occurs, data are simultaneously transferred from an 8-bit SFR to memory, a 16-bit SFR to memory (word), memory (byte) to an 8-bit SFR, and memory (word) to a 16-bit SFR (3 points MAX. for each transfer).

This mode can also be used to exchange data, instead of transferring data.

This mode can be used for automatic transfer/reception by the serial interface or automatic updating of data/timing by the serial output port.

When the value of the macro service counter reaches to 0, a vector interrupt occurs.





(3) Macro service type A

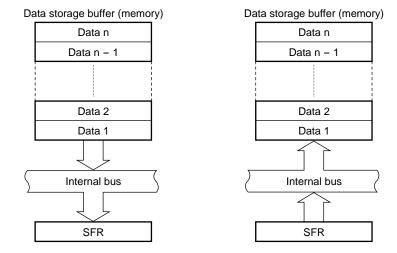
When an interrupt occurs, data is transferred from an 8-/16-bit SFR to memory (byte/word) or from memory (byte/word) to an 8-/16-bit SFR.

Data is transferred the number of times set in advance by the macro service counter.

This mode can be used to store the result of A/D conversion or for automatic transfer (or reception) by the serial interface.

Because transfer data is stored at an address FE00H to FEFFH, if only a small quantity of data is to be transferred, the data can be transferred at high speeds.

When the value of the macro service counter is decremented to 0, a vector interrupt occurs.

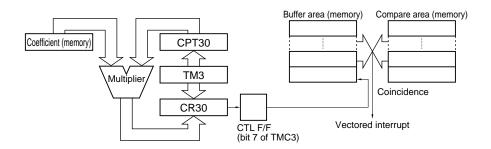


(4) Data pattern identification mode (VISS detection mode)

This mode of macro service is for detection of the VISS signal and is used in combination with a pulse width detection circuit.

When an interrupt occurs, the content of bit 7 of an SFR (usually, TMC3) specified by SFR pointer 1 is shifted into the buffer area. At the same time, the data in the buffer area is compared with the data in the compare area. If the two data coincide, an interrupt request is generated. When the value of the macro service counter is decremented to 0, a vector interrupt occurs.

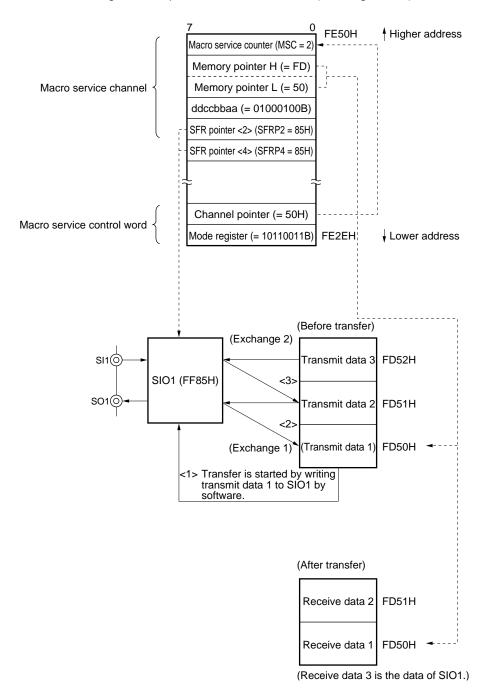
It can be specified by option that the value of an SFR (usually, CPT30) specified by SFR pointer 2 be multiplied by a coefficient and the result of this multiplication be stored to an SFR (usually, CR30) specified by SFR pointer 3 (this operation is to automatically update an identification threshold value when the tape speed fluctuates).



4.1.4 Application Example of Macro Service

(1) Automatic transfer/reception of serial interface

Automatic transfer/reception of 3-byte data by serial interface channel 1 Setting of macro service register: compound data transfer mode (exchange mode)

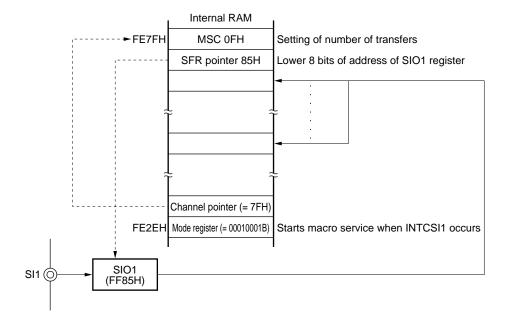




(2) Reception operation of serial interface

Transfer of receive data by serial interface channel 1 (16 bytes)

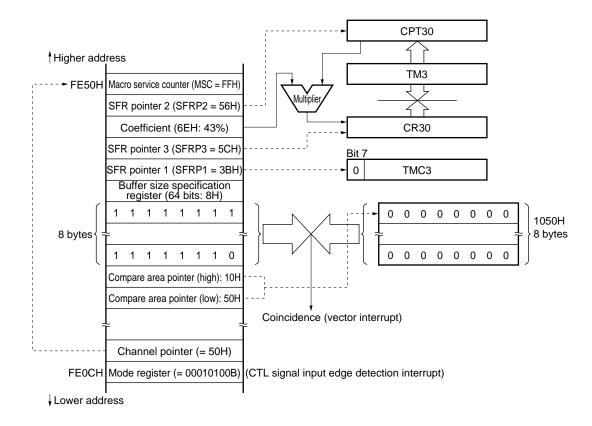
Setting of macro service mode register: macro service type A (1-byte transfer from SFR to memory)





(3) VISS detection operation

Setting of macro service mode register: data pattern identification mode (with multiplication, 8-byte comparison)





4.2 STANDBY FUNCTION

The standby function is to reduce the power consumption of the chip and is used in the following modes:

Mode	Function						
HALT mode	Stops operating clock of CPU. Reduces average power consumption						
	when used in combination with normal mode for intermittent operation						
STOP mode	Stops oscillator. Stops all internal operations of chip to minimize power						
	consumption to leakage current only						
Low power consumption mode	Stops main system clock with subsystem clock used as system clock.						
	CPU can operate with subsystem clock to reduce power consumption						
Low power consumption HALT mode	Standby function in low power consumption mode. Stops operating clock						
	of CPU. Reduces power consumption of overall system						

These modes are programmable.

The macro service can be started in the HALT mode.

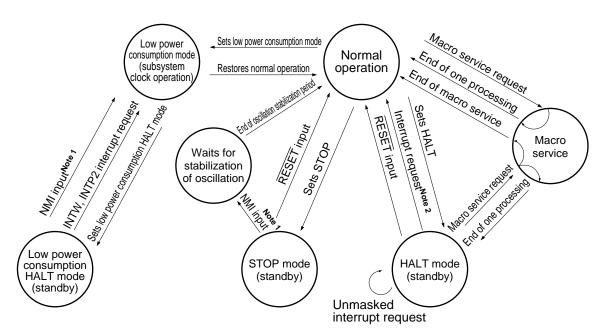


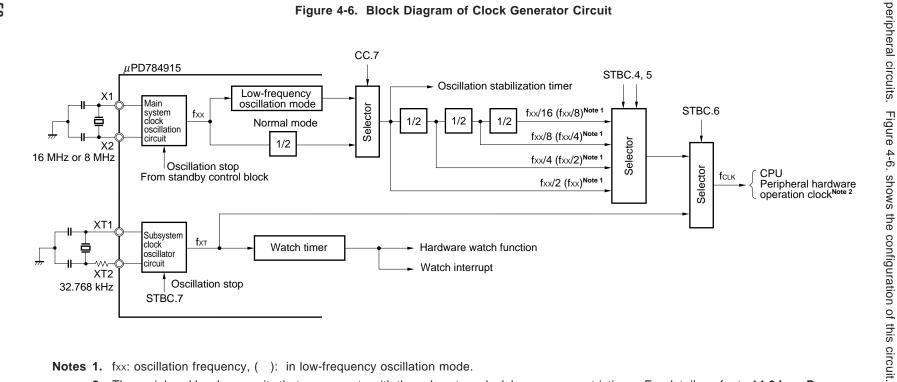
Figure 4-4. Status Transition of Standby Function

Notes 1. NMI input means starting NMI by NMI pin input, watch interrupt, or key interrupt input.

2. Unmasked interrupt request

INTM0.0 Standby control block Selector NMI () Latch Interrupt control block Clear INTP1 ◎ INTP2 ◎ KEY0 ◎ KEY1 O-KEY2 O-_ Q → KEYC.7 S KEY3 ◎-R KEY4 ◎-Cleared when "0" is written to KEYC.7 Mask KEYC.6 → KEYC.0 KEYC.5 Q Mask Mask KEYC.4 R WM.6 Cleared when "0" is written to KEYC.0 Watch timer INTW (OVF) Selector Divides INTW by 128 (HW0L.7) Mask WM.3

Figure 4-5. Relations among NMI, Watch Interrupt, and Key Interrupt When STOP Mode Is Released



- Notes 1. fxx: oscillation frequency, (): in low-frequency oscillation mode.
 - 2. The peripheral hardware units that can operate with the subsystem clock have some restrictions. For details, refer to 14.6 Low Power Consumption Mode in μ PD784915 Subseries User's Manual.



4.4 RESET FUNCTION

When a low-level signal is input to the RESET pin, the system is reset, and each hardware unit is initialized (reset status). During the reset period, oscillation of the system clock is unconditionally stopped, so that the current dissipation of the overall system can be reduced.

When the RESET pin goes high, the reset status is cleared. After the count time of the oscillation stabilization timer (32.8 ms at 16 MHz or 65.6 ms at 8 MHz) has elapsed, the contents of the reset vector table are set to the program counter (PC), and execution branches to the address set to the PC, and the program is executed starting from the branch destination address. Therefore, execution can be reset and started from any address.

Main system clock oscillation circuit

During reset, oscillation is unconditionally stopped.

FCLT

Oscillation stabilization timer count time

Figure 4-7. Oscillation of Main System Clock during Reset Period

The RESET pin is provided with an analog delay noise rejecter circuit to prevent malfunctioning due to noise.

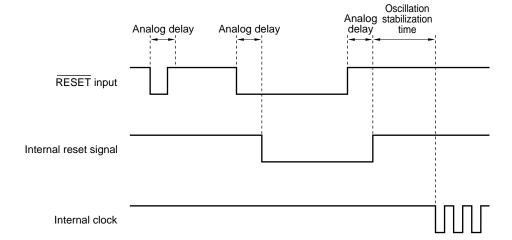


Figure 4-8. Accepting Reset Signal



5. INSTRUCTION SET

(1) 8-bit instructions ((): combination realized by describing A as r)

MOV, XCH, ADD, ADDC, SUB, SUBC, AND, OR, XOR, CMP, MULU, DIVUW, INC, DEC, ROR, ROL, RORC, ROLC, SHR, SHL, ROR4, ROL4, DBNZ, PUSH, POP, MOVM, XCHM, CMPME, CMPMNE, CMPMNC, CMPMC, MOVBK, XCHBK, CMPBKNE, CMPBKNE, CMPBKNC, CMPBKC, CHKL, CHKLA

2nd Operand	# byte	А	r	saddr	sfr	!addr16	mem	r3	[WHL+]	[WHL-]	n	None Note 2
			r'	saddr'		!!addr24	[saddrp]	PSWL				
1st Operand \							[%saddrg]	PSWH				
A	(MOV)	(MOV)	MOV	(MOV)Note 6	MOV	(MOV)	MOV	MOV	(MOV)	(MOV)		
	ADD ^{Note 1}	(XCH)	XCH	(XCH)Note 6	(XCH)	(XCH)	XCH		(XCH)	(XCH)		
		(ADD)Note 1	(ADD)Note 1	(ADD)Note 1,6	(ADD)Note 1	ADDNote 1	ADDNote 1		(ADD)Note 1	(ADD)Note 1		
r	MOV	(MOV)	MOV	MOV	MOV	MOV					RORNote 3	MULU
	ADD ^{Note 1}	(XCH)	хсн	XCH	хсн	XCH						DIVUW
		(ADD)Note 1	ADDNote 1	ADDNote 1	ADD ^{Note 1}							INC
												DEC
saddr	MOV	(MOV)Note 6	MOV	MOV								INC
	ADD ^{Note 1}	(ADD)Note 1	ADD ^{Note 1}	XCH								DEC
				ADD ^{Note 1}								DBNZ
sfr	MOV	MOV	MOV									PUSH
	ADDNote 1	(ADD)Note 1	ADDNote 1									POP
												CHKL
												CHKLA
!addr16	MOV	(MOV)	MOV									
!!addr24		ADD ^{Note 1}										
mem		MOV										
[saddrp]		ADDNote 1										
[%saddrg]												
mem3												ROR4
												ROL4
r3	MOV	MOV										
PSWL												
PSWH												
B, C												DBNZ
STBC, WDM	MOV											
[TDE+]		(MOV)							MOVBKNote 5			
		(ADD) ^{Note 1}										
		MOVMNote 4										
[TDE-]		(MOV)								MOVBKNote 5		
		(ADD)Note 1										
		MOVMNote 4										

Notes 1. ADDC, SUB, SUBC, AND, OR, XOR, and CMP are the same as ADD.

- 2. Either the second operand is not used, or the second operation is not an operand address.
- 3. ROL, RORC, ROLC, SHR, and SHL are the same as ROR.
- 4. XCHM, CMPME, CMPMNE, CMPMNC, and CMPMC are the same as MOVM.
- 5. XCHBK, CMPBKE, CMPBKNE, CMPBKNC, and CMPBKC are the same as MOVBK.
- 6. If saddr2 instead of saddr is used in this combination, the code length of some instructions is short.



(2) 16-bit instructions ((): combination realized by describing AX as rp)

MOVW, XCHW, ADDW, SUBW, CMPW, MULUW, MULW, DIVUX, INCW, DECW, SHRW, SHLW, PUSH, POP, ADDWG, SUBWG, PUSHU, POPU, MOVTBLW, MACW, MACSW, SACW

2nd Operand	# word	AX	rp	saddrp	sfrp	!addr16	mem	[WHL+]	byte	n	None Note 2
			rp'	saddrp'		!!addr24	[saddrp]				
1st Operand \							[%saddrg]				
AX	(MOVM)	(MOVW)	(MOVW)	(MOVW)Note 3	MOVW	(MOVW)	MOVW	(MOVW)			
	ADDW ^{Note 1}	(XCHW)	(XCHW)	(XCHW)Note 3	(XCHW)	XCHW	XCHW	(XCHW)			
		(ADDW)Note 1	(ADDW)Note 1	(ADDW)Note 1,3	(ADDW)Note 1						
rp	MOVW	(MOVW)	MOVW	MOVW	MOVW	MOVW				SHRW	MULWNote 4
	ADDW ^{Note 1}	(XCHW)	XCHW	XCHW	XCHW					SHLW	INCW
		(ADDW)Note 1	ADDW ^{Note 1}	ADDW ^{Note 1}	ADDW ^{Note 1}						DECW
saddrp	MOVW	(MOVW)Note 3	MOVW	MOVW							INCW
	ADDW ^{Note 1}	(ADDW)Note 1	ADDWNote 1	XCHW							DECW
				ADDW ^{Note 1}							
sfrp	MOVW	MOVW	MOVW								PUSH
	ADDW ^{Note 1}	(ADDW)Note 1	ADDW ^{Note 1}								POP
!addr16	MOVW	(MOVW)	MOVW						MOVTBLW		
!!addr24											
mem		MOVW									
[saddrp]											
[%saddrg]											
PSW											PUSH
											POP
SP	ADDWG										
	SUBWG										
post											PUSH
											POP
											PUSHU
											POPU
[TDE+]		(MOVW)						SACW			
byte											MACW
											MACSW

Notes 1. SUBW and CMPW are the same as ADDW.

- 2. Either the second operand is not used, or the second operation is not an operand address.
- 3. If saddr2 instead of saddr is used in this combination, the code length of some instructions is short.
- 4. MULUW and DIVUX are the same as MULW.



(3) 24-bit instructions ((): combination realized by describing WHL as rg) MOVG, ADDG, SUBG, INCG, DECG, PUSH, POP

2nd Operand	# imm24	WHL	rg	saddrg	!!addr24	mem1	[%saddrg]	SP	None ^{Note}
			rg'						
1st Operand									
WHL	(MOVG)	(MOVG)	(MOVG)	(MOVG)	(MOVG)	MOVG	MOVG	MOVG	
	(ADDG)	(ADDG)	(ADDG)	ADDG					
	(SUBG)	(SUBG)	(SUBG)	SUBG					
rg	MOVG	(MOVG)	MOVG	MOVG	MOVG				INCG
	ADDG	(ADDG)	ADDG						DECG
	SUBG	(SUBG)	SUBG						PUSH
									POP
saddrg		(MOVG)	MOVG						
!!addr24		(MOVG)	MOVG						
mem1		MOVG							
[%saddrg]		MOVG							
SP	MOVG	MOVG							INCG
									DECG

Note Either the second operand is not used, or the second operation is not an operand address.

(4) Bit manipulation instructions

MOV1, AND1, OR1, XOR1, SET1, CLR1, NOT1, BT, BF, BTCLR, BFSET

2nd Operand	CY	saddr.bit	/saddr.bit	None ^{Note}
		sfr.bit	/sfr.bit	
		A.bit	/A.bit	
		X.bit	/X.bit	
		PSWL.bit	/PSWL.bit	
		PSWH.bit	/PSWH.bit	
		mem2.bit	/mem2.bit	
		iaddr16.bit	/!addr16.bit	
1st Operand		!addr24.bit	/!!addr24.bit	
CY		MOV1	AND1	NOT1
		AND1	OR1	SET1
		OR1		CLR1
		XOR1		
saddr.bit	MOV1			NOT1
sfr.bit				SET1
A.bit				CLR1
X.bit				BF
PSWL.bit				ВТ
PSWH.bit				BTCLR
mem2.bit				BFSET
!addr16.bit				
!!addr24.bit				

Note Either the second operand is not used, or the second operation is not an operand address.



(5) Call/return and branch instructions

CALL, CALLF, CALLT, BRK, RET, RETI, RETB, RETCS, RETCSB, BRKCS, BR, BNZ, BNE, BZ, BE, BNC, BNL, BC, BL, BNV, BPO, BV, BPE, BP, BN, BLT, BGE, BLE, BGT, BNH, BH, BF, BT, BTCLR, BFSET, DBNZ

Operand of	\$addr20	\$!addr20	!addr16	!!addr20	rp	rg	[rp]	[rg]	!addr11	[addr5]	RBn	None
instruction												
address												
Basic	BCNote	CALL	CALL	CALL	CALL	CALL	CALL	CALL	CALLF	CALLT	BRKCS	BRK
instruction	BR	BR	BR	BR	BR	BR	BR	BR				RET
			RETCS									RETI
			RETCSB									RETB
Compound	BF											
instruction	вт											
	BTCLR											
	BFSET											
	DBNZ											

Note BNZ, BNE, BZ, BE, BNC, BNL, BL, BNV, BPO, BV, BPE, BP, BN, BLT, BGE, BLE, BGT, BNH, and BH are the same as BC.

(6) Other instructions

ADJBA, ADJBS, CVTBW, LOCATION, SEL, NOT, EI, DI, SWRS



6. ELECTRICAL CHARACTERISTICS (TARGETED VALUE)

Absolute Maximum Ratings (T_A = 25 °C)

Parameter Symbol Condition Ratings Unit Supply voltage V_{DD} $|V_{DD} - AV_{DD1}| \le 0.5 V$ -0.5 to +7.0V AV_{DD1} $|V_{DD} - AV_{DD2}| \le 0.5 V$ -0.5 to +7.0٧ AV_{DD2} $|AV_{DD1} - AV_{DD2}| \le 0.5 \text{ V}$ -0.5 to +7.0٧ AVss1 -0.5 to +0.5٧ AVss2 -0.5 to +0.5V V١ -0.5 to V_{DD} + 0.5 ٧ Input voltage Analog input voltage -0.5 to AV_{DD2} + 0.5 VIAN $V_{DD} \ge AV_{DD2}$ V (ANIO-ANI11) $V_{DD} < AV_{DD2}$ -0.5 to V_{DD} + 0.5 ٧ Output voltage Vo -0.5 to V_{DD} + 0.5 V Low-level output current Pin 1 15 mΑ lol Total of all pins 100 mΑ High-level output current Іон Pin 1 -10 mΑ Total of all pins -50 mΑ Operating ambient temperature TΑ °С -10 to +70 -65 to +150 °С Storage temperature Tstg

Caution If the rated value of even one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings therefore specify the values exceeding which the product may be physically damaged. Never exceed these values when using the product.

Operating Conditions

Clock Frequency	Operating Temperature (TA)	Operating Conditions	Supply Voltage (VDD)
4 MHz ≤ fxx ≤ 16 MHz	−10 to +70 °C	All functions	+4.5 to +5.5 V
		CPU function only	+4.0 to +5.5 V
32 kHz ≤ fxτ ≤ 35 kHz		Subclock operation	+2.7 to +5.5 V
		(CPU, watch, and port	
		functions only)	



Oscillator Characteristics (main clock) (TA = -10 to +70 °C, VDD = AVDD = 4.0 to 5.5 V, Vss = AVss = 0 V)

Oscillator	Recommended Circuit	Parameter	MIN.	MAX.	Unit
Crystal oscillator	X1 X2 Vss ——————————————————————————————————	Oscillation frequency (fxx)	4	16	MHz

Oscillator Characteristics (subclock) (TA = -10 to +70 °C, VDD = AVDD = 2.7 to 5.5 V, Vss = AVss = 0 V)

Oscillator	Recommended Circuit	Parameter	MIN.	MAX.	Unit
Crystal oscillator	X1 X2 Vss C1 C2	Oscillation frequency (fxT)	32	35	kHz

Caution When using the main system clock and subsystem clock oscillation circuits, wire the portion enclosed by the broken line in the above figures as follows to avoid the adverse influence of wiring capacitance:

- Keep the wiring length as short as possible.
- Do not cross the wiring with the other signal lines. Do not route the wiring in the neighborhood of a signal line through which a high alternating current flows.
- Always keep the ground point of the capacitor of the oscillator circuit to the same potential as Vss. Do not ground the capacitor to a ground pattern to which a high current flows.
- Do not extract signals from the oscillation circuit.

Exercise particular care in using the subsystem clock oscillation circuit because the amplification factor of this circuit is kept low to reduce the current consumption.



DC Characteristics (Ta = -10 to +70 °C, VdD = AVdD = 4.5 to 5.5 V, Vss = AVss = 0 V)

_	T						T
Parameter	Symbol		Conditions	MIN.	TYP.	MAX.	Unit
Low-level input voltage	V _{IL1}		an those listed in Note 1 below	0		0.3 V _{DD}	V
	V _{IL2}		Note 1 below	0		0.2 V _{DD}	V
	VIL3	X1, X2		0		0.4	V
High-level input voltage	V _{IH1}	-	an those listed in Note 1 below	0.7 Vdd		VDD	V
	V _{IH2}	Pins listed in	Note 1 below	0.8 Vdd		V _{DD}	V
	VIH3	X1, X2		VDD - 0.5		Vdd	V
Low-level output voltage	V _{OL1}	loL = 5.0 mA	(pins in Note 2)			0.6	V
	V _{OL2}	IoL = 2.0 mA				0.45	V
	Vol3	IoL = 100 μA				0.25	V
High-level output voltage	V _{OH1}	Iон = −1.0 m	A	V _{DD} - 1.0			V
	V _{OH2}	Іон = -100 μ	он = $-100 \ \mu A$				V
Input leakage current	Li	$0 \le V_I \le V_{DD}$) ≤ Vı ≤ V _{DD}			±10	μΑ
Output leakage current	ILO	0 ≤ Vo ≤ VDD				±10	μΑ
V _{DD} supply current	I _{DD1}	Operation	fxx = 16 MHz		30	50	mA
		mode	fxx = 8 MHz (low-frequency os-				
			cillation mode)				
			Internally, 8-MHz main system				
			clock operation				
			fxt = 32.768 kHz		50	80	μΑ
			Subclock operation (CPU,				"
			watch, port)				
			V _{DD} = 2.7 V				
	I _{DD2}	HAIT mode	fxx = 16 MHz		10	25	mA
	1002	TIALT MODE	$f_{xx} = 8 \text{ MHz (low-frequency)}$		10	20	111/5
			oscillation mode)				
			,				
			Internally, 8-MHz main clock				
			operation		25	50	
			fxt = 32.768 MHz		25	50	μΑ
			Subclock operation (CPU,				
			watch, port)				
	ļ.,		V _{DD} = 2.7 V				
Data hold voltage	VDDDR	STOP mode	T	2.5			V
Data hold current Note 3	IDDDR		Subclock oscillates		18	50	μΑ
		VDDDR = 5.0 V					
			Subclock oscillates		1.5	10	μΑ
		VDDDR = 2.7 V					
			Subclock stops		0.2	7.0	μΑ
		VDDDR = 2.5 V					
Pull-up resistor	R∟	V1 = 0 V		25	55	110	kΩ

Notes 1. RESET, IC, NMI, INTP0-INTP2, P61/SCK1/BUZ, P63/SI1, SCK2, SI2/BUSY, P65/HWIN, P91/KEY0-P95/KEY4

- **2.** P46, P47
- **3.** In the STOP mode in which the subclock oscillation is stopped, disconnect the feedback resistor, and connect the XT1 pin to V_{DD}.



AC Characteristics

CPU and peripheral circuit operation clock (Ta = -10 to +70 °C, V_{DD} = AV_{DD} = 4.5 to 5.5 V, Vss = AV_{SS} = 0 V)

Parameter	Symbol		Condition	TYP.	Unit
CPU operation clock cycle time	tclk	fxx = 16 MHz	$V_{DD} = AV_{DD} = 4.0 \text{ to } 5.5 \text{ V}$	125	ns
			CPU Function only		
		fxx = 16 MHz	xx = 16 MHz		
		fxx = 8 MHz	low-frequency oscillation mode		
			(Bit 7 of CC = 1)		
Peripheral operation clock cycle time	tclk1	fxx = 16 MHz		125	ns
		fxx = 8MHz	low-frequency oscillation mode		
			(Bit 7 of CC = 1)		

Serial interface

(1) SIOn: n = 1 or 2 (TA = -10 to +70 °C, VDD = AVDD = 4.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol		Condition	MIN.	MAX.	Unit
Serial clock cycle time	tcysk	Input	External clock	1.0		μs
		Output	fcLK1/8	1.0		μs
			fclk1/16	2.0		μs
			fcLK1/32	4.0		μs
			fclk1/64	8.0		μs
			fclk1/128	16		μs
			fclk1/256	32		μs
Serial clock high- and low-level widths	twsĸн	Input	External clock	420		ns
	twskL	Output	Internal clock	tcysk/2 - 50		ns
SIn setup time (vs. SCKn ↑)	tsssk			100		ns
SIn hold time (vs. SCKn ↑)	thssk			400		ns
SOn output delay time (vs. SCKn ↓)	tossk			0	300	ns

Remarks 1. fclk1: operating clock of peripheral circuit (8 MHz)

2. n = 1 or 2

(2) SIO2 only (TA = -10 to +70 $^{\circ}$ C, VDD = AVDD = 4.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	MAX.	Unit
SCK2(8) ↑→STBR ↑	tdstrb		twskH	tcysk	
Strobe high-level width	twstrb		tсүзк — 30	tcүsк + 30	ns
BUSY setup time	tsbusy		100		ns
(vs. BUSY detection timing)					
BUSY hold time	tнвиsy		100		ns
(vs. BUSY detection timing)					
BUSY inactive → SCK2(1) ↓	tlbusy			tcysk + twskh	

Remarks 1. The value in () following SCK2 indicates the number of SCK2.

- 2. BUSY is detected after the time of (n+2) x tcysk (n = 0, 1, and so on) in respect to $\overline{SCK2}$ (8) \uparrow .
- **3.** BUSY inactive $\rightarrow \overline{SCK2}$ (1) \downarrow is the value when data has been completely written to SIO2.



Other operations (TA = -10 to +70 °C, VDD = AVDD = 4.5 to 5.5 V, Vss = AVss = 0 V)

F	Parameter	Symbol	С	ondition	MIN.	MAX.	Unit
Timer input sign	al low-level width	twcTL	When DFGIN, CFC	GIN, DPGIN, REEL0IN,	tclk1		ns
			or REEL1IN logic I	evel is input			
Timer input sign	al high-level width	twcтн	When DFGIN, CFC	GIN, DPGIN, REEL0IN,	tclk1		ns
			or REEL1IN logic I	evel is input			
Timer input sign	al valid edge input cycle	t PERIN	When DFGIN, CF	GIN, or DPGIN is input	2		μs
CSYNCIN low-le	evel width	twcr1L	When digital noise r	ejecter circuit is not used	8tclk1		ns
			When digital noise	rejecter circuit is used	108tclk1		ns
			(Bit 4 of INTM2 = 0))			
			When digital noise	rejecter circuit is used	180tclk1		ns
			(Bit 4 of INTM2 = 1	1)			
CSYNCIN high-level width		twcr1H	When digital noise r	ejecter circuit is not used	8tclk1		ns
			When digital noise	rejecter circuit is used	108tclk1		ns
			(Bit 4 of INTM2 = 0))			
			When digital noise	rejecter circuit is used	180tclk1		ns
			(Bit 4 of INTM2 = 1	1)			
Digital noise	Rejected pulse width	twsep	Bit 4 of INTM2 = 0	·		104tclk1	ns
rejecter circuit			Bit 4 of INTM2 = 1			176tclk1	ns
	Passed pulse width		Bit 4 of INTM2 = 0		108tclk1		ns
			Bit 4 of INTM2 = 1		180tcLK1		ns
NMI low-level w	idth	twnil	VDD = AVDD = 2.7 to	o 5.5 V	10		μs
NMI high-level v	vidth	twnih	V _{DD} = AV _{DD} = 2.7 to 5.5 V		10		μs
INTP0, INTP3 ld	ow-level widths	twiplo			2tclk1		ns
INTP0, INTP3 h	igh-level widths	twipho			2tclk1		ns
INTP1, KEY0-K	EY4 low-level widths	twipL1	Mode other than S	TOP mode	2tclk1		ns
			In STOP mode, for	releasing STOP mode	10		μs
INTP1, KEY0-K	EY4 high-level widths	twiph1	Mode other than S	TOP mode	2tclk1		ns
			In STOP mode, for	releasing STOP mode	10		μs
INTP2 low-level	width	twipl2	In normal mode,	Sampling = fclk	2tclk1		ns
			with main clock	Sampling = fclk/128	32Note		μs
			Normal mode,	Sampling = fclk	61		μs
			with subclock	Sampling = fclk/128	7.9 ^{Note}		ms
			In STOP mode, for	releasing STOP mode	10		μs
INTP2 high-lev	el width	twiph2	In normal mode,	Sampling = fclk	2tclk1		ns
			with main clock	Sampling = fclk/128	32Note		μs
			Normal mode,	Sampling = fclk	61		μs
			with subclock	Sampling = fclk/128	7.9 ^{Note}		ms
			In STOP mode, for	releasing STOP mode	10		μs
RESET low-leve	el width	twrsl			10		μs

Note If a high or low level is successively input two times during the sampling period, a high or low level is detected.

Remark tckl1: operating clock cycle time of peripheral circuit (125 ns)



Clock output operation (TA = -10 to +70 °C, VDD = AVDD = 4.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	MAX.	Unit
CLO cycle time	tcycL		250	2000	ns
CLO low-level width	tcll	tcycL/2 ± 50	75	1050	ns
CLO high-level width	t clH	tcycL/2 ± 50	75	1050	ns
CLO rise time	tclr			50	ns
CLO fall time	tclf			50	ns

Data hold characteristics (TA = -10 to +70 °C, VDD = AVDD = 2.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Low-level input voltage	VIL	Special pins (pins in Note)	0		0.1 VDDDR	V
High-level input voltage	ViH		0.9 VDDDR	·	VDDDR	V

Note RESET, IC, NMI, INTP0-INTP2, P61/SCK1/BUZ, P63/SI1, SCK2, SI2/BUSY, P65/HWIN P91/KEY0-P95/KEY4

Watch function (T_A = -10 to +70 °C, V_{DD} = AV_{DD} = 2.7 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	MAX.	Unit
Subclock oscillation hold voltage	VDDXT		2.7		V
Hardware watch function operating voltage	V _{DDW}		2.7		V

Subclock oscillation stop detection flag (TA = -10 to +70 °C, VDD = AVDD = 4.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	MAX.	Unit
Oscillation stop detection width	toscf		45		μs

A/D converter characteristics (TA = -10 to +70 °C, VDD = AVDD = AVREF = 4.5 to 5.5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Resolution			8			bit
Total error		AVREF = VDD			2.0	%
Quantization error					±1/2	LSB
Conversion time	tconv	Bit 4 of ADM = 0	160tcLK1			μs
		Bit 4 of ADM = 1	80tcLK1			μs
Sampling time	tsamp	Bit 4 of ADM = 0	32tcLK1			μs
		Bit 4 of ADM = 1	16tcLK1			μs
Analog input voltage	VIAN		0		AVREF	V
Analog input impedance	Zan			1000		МΩ
AV _{REF} current	Alref			0.4	1.2	mA

VREF amplifier (TA = 25 $^{\circ}$ C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Reference voltage	VREF		2.35	2.50	2.65	V
Charge current	Існв	Sets AMPM0.0 to 1	300			μΑ
		(pins in Note)				

Note RECCTL+, RECCTL-, CFGIN, CFGCPIN, DFGIN, DPGIN, CSYNCIN, REEL0IN, REEL1IN



CTL amplifier (TA = 25 $^{\circ}$ C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
CTL+, - input resistance	RICTL		2	5	10	kΩ
Feedback resistance	RFCTL		20	50	100	kΩ
Bias resistance	RBCTL		20	50	100	kΩ
Minimum voltage gain	GCTLMIN		17	20	22	dB
Maximum voltage gain	G CTLMAX		71	75		dB
Gain selecting step	SGAIN			1.77		dB
Same phase signal elimination ratio	CMR	DC, voltage gain: 20 dB		50		dB
High comparator set voltage of waveform shaping	VPBCTLHS		VREF + 0.47	Vref + 0.50	VREF + 0.53	V
High comparator reset voltage of waveform shaping	VPBCTLHR		VREF + 0.27	Vref + 0.30	VREF + 0.33	V
Low comparator set voltage of waveform shaping	VPBCTLLS		VREF - 0.53	Vref - 0.50	Vref - 0.47	V
Low comparator reset voltage of waveform shaping	VPBCTLLR		V _{REF} - 0.33	Vref - 0.30	Vref - 0.27	V
High comparator voltage of CTL flag S	VFSH		VREF + 1.00	Vref + 1.05	VREF + 1.10	V
Low comparator voltage of CLT flag S	V _{FSL}		VREF - 1.10	Vref - 1.05	Vref - 1.00	V
High comparator voltage of CTL flag L	V _{FLH}		VREF + 1.40	Vref + 1.45	Vref + 1.50	V
Low comparator voltage of CTL flag L	VFLL		V _{REF} – 1.50	VREF - 1.45	V _{REF} – 1.40	V

CFG amplifier (AC coupling) (TA = 25 $^{\circ}$ C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

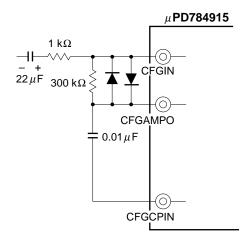
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Voltage gain 1	G _{CFG1}	fi = 2 kHz, open loop	50			dB
Voltage gain 2	G _{CFG2}	fi = 30 kHz, open loop	34			dB
CFGAMPO High-level output current	Іонсға	DC	-1			mA
CFGAMPO Low-level output current	lolcfg	DC	0.4			mA
High comparator voltage	VcFGH		VREF + 0.09	V _{REF} + 0.12	Vref + 0.15	V
Low comparator voltage	VcFGL		Vref - 0.15	Vref - 0.12	V _{REF} - 0.09	V
Duty accuracy	PDUTY	Note	49.7	50.0	50.3	%

Note The conditions include the following circuit and input signal.

Input signal : Sine wave input (5 mV $_{p-p}$)

 $f_i = 1 \text{ kHz}$

Voltage gain: 50 dB



*



DFG amplifier (AC coupling) (TA = 25 °C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Voltage gain	GDFG	fi = 900 Hz, open loop	50			dB
Feedback resistance	RFDFG		160	400	640	kΩ
Input protection resistance	Ridfg			150		Ω
High comparator voltage	VDFGH		VREF + 0.07	VREF + 0.10	VREF + 0.14	V
Low comparator voltage	VDFGL		VREF - 0.14	Vref - 0.10	VREF - 0.07	V

Caution Set the input resistance connected to the DFGIN pin to 16 $k\Omega$ or below. Connecting a resistor exceeding that value may cause the DFG amp to oscillate.

DPG comparator (AC coupling) (TA = 25 °C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input impedance	ZIDPG		20	50	100	kΩ
High comparator voltage	VDPGH		VREF + 0.02	VREF + 0.05	VREF + 0.08	V
Low comparator voltage	VDPGL		V _{REF} - 0.08	V _{REF} - 0.05	V _{REF} - 0.02	V

Ternary separation circuit (TA = 25 $^{\circ}$ C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input impedance	ZIPFG		20	50	100	kΩ
High comparator voltage	Vpfgh		VREF + 0.5	VREF + 0.7	V _{REF} + 0.9	V
Low comparator voltage	Vpfgl		VREF - 1.4	VREF - 1.2	V _{REF} – 1.0	٧

CSYNC comparator (AC coupling) ($T_A = 25$ °C, $V_{DD} = AV_{DD} = 5$ V, $V_{SS} = AV_{SS} = 0$ V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input impedance	ZICSYN		20	50	100	kΩ
High comparator voltage	Vcsynh		VREF + 0.07	VREF + 0.10	V _{REF} + 0.13	V
Low comparator voltage	VCSYNL		VREF - 0.13	Vref - 0.10	V _{REF} - 0.07	V

Reel FG comparator (AC coupling) ($T_A = 25 \, ^{\circ}C$, $V_{DD} = AV_{DD} = 5 \, V$, $V_{SS} = AV_{SS} = 0 \, V$)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input impedance	Zirlfg		20	50	100	kΩ
High comparator voltage	VRLFGH		V _{REF} + 0.02	VREF + 0.05	VREF + 0.08	V
Low comparator voltage	VRLFGL		Vref - 0.08	Vref - 0.05	V _{REF} - 0.02	V

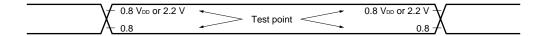
RECCTL driver (TA = 25 $^{\circ}$ C, VDD = AVDD = 5 V, Vss = AVss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
RECCTL+, - high-level output voltage	VCHREC	lон = −4 mA	VDD - 0.8			V
RECCTL+, - low-level output voltage	Volrec	IoL = 4 mA			0.8	V
CTLDLY internal resistance	Rctl		40	70	140	kΩ
CTLDLY charge current	Іонсть	Use of internal resistor	-3			mA
CTLDLY discharge current	Іостть		-3			mA

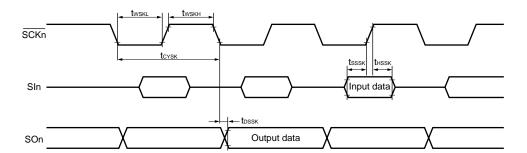


Timing waveform

AC timing test point



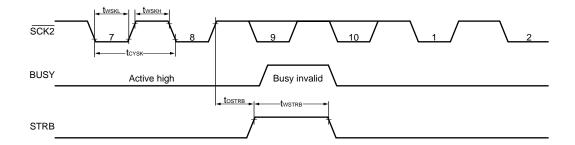
Serial transfer timing (SIOn: n = 1 or 2)



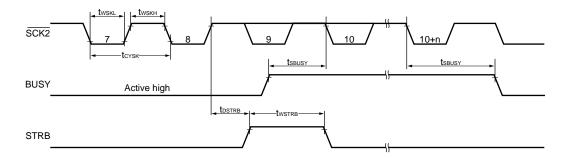


Serial transfer timing (SIO2 only)

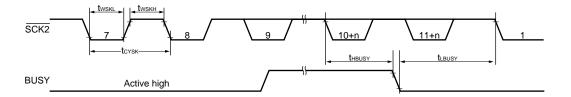
No busy processing



Continuation of busy processing



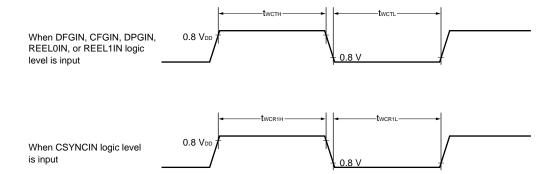
End of busy processing



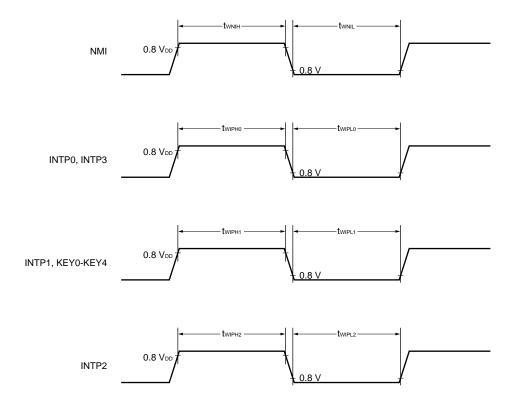
Caution When an external clock is selected as the serial clock, do not use the busy control or strobe control.



Super timer unit input timing



Interrupt input timing

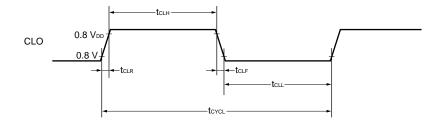


Reset input timing





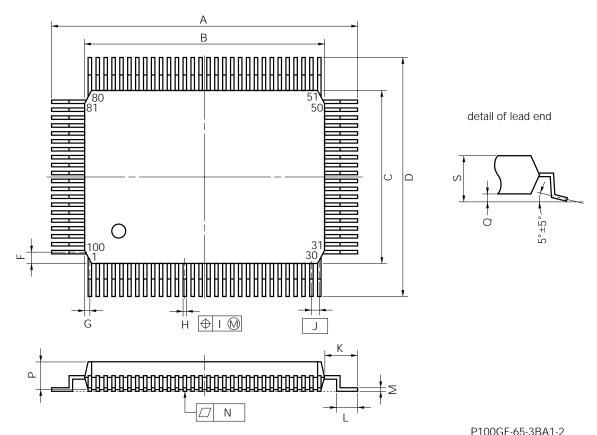
Clock output timing





7. PACKAGE DRAWING

100 PIN PLASTIC QFP (14 × 20)



NOTE

Each lead centerline is located within 0.15 mm (0.006 inch) of its true position (T.P.) at maximum material condition.

P100GF-05-3DA1		
ITEM	MILLIMETERS	INCHES
А	23.6±0.4	0.929±0.016
В	20.0±0.2	$0.795^{+0.009}_{-0.008}$
С	14.0±0.2	0.551+0.009
D	17.6±0.4	0.693±0.016
F	0.8	0.031
G	0.6	0.024
Н	0.30±0.10	0.012+0.004
I	0.15	0.006
J	0.65 (T.P.)	0.026 (T.P.)
K	1.8±0.2	$0.071^{+0.008}_{-0.009}$
L	0.8±0.2	0.031+0.009
М	0.15 ^{+0.10} _{-0.05}	0.006+0.004
N	0.10	0.004
Р	2.7	0.106
Q	0.1±0.1	0.004±0.004
S	3.0 MAX.	0.119 MAX.



8. RECOMMENDED SOLDERING CONDITIONS

The conditions listed below shall be met when sholdering the μ PD784915.

For details of the recommended soldering conditions, refer to our document **Semiconductor Device Mounting Technology Manual (C10535E)**.

Please consult with our sales offices in case any other soldering process is used, or in case soldering is done under different conditions.

Table 8-1. Soldering Conditions for Surface-Mount Type

 μ PD784915GF-3BA: 100-pin plastic QFP (14 imes 20 mm)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 235 °C, Duration: 30 sec. max. (at 210 °C or above),	IR35-00-2
	Number of times: Twice max.	
	<points note="" to=""></points>	
	(1) Start the second reflow after the device temperature by the first reflow returns	
	to normal.	
	(2) Flux washing by the water after the first reflow should be avoided.	
VPS	Package peak temperature: 215 °C, Duration: 40 sec. max. (at 200 °C or above),	VP15-00-2
	Number of times: Twice max.	
	<points note="" to=""></points>	
	(1) Start the second reflow after the device temperature by the first reflow returns	
	to normal.	
	(2) Flux washing by the water after the first reflow should be avoided.	
Wave soldering	Solder bath temperature: 260 °C max. Duration: 10 sec. max.	WS60-00-1
	Number of times: Once	
	Preliminary heat temperature: 120 °C max. (Package surface temperature)	
Partial heating	Pin temperature: 300 °C max., Duration: 3 sec. max. (per device side)	_

Caution Using more than one soldering method should be avoided (except in the case of partial heating).



APPENDIX A. DEVELOPMENT TOOLS

The following development tools are available for system development using $\mu PD784915$.

Language Processing Software

RA78K4 ^{Note 1}	78K/IV series common assembler package
CC78K4Note 1	78K/IV series common C compiler package
CC78K4-LNote 1	78K/IV series common C compiler library source file

PROM Writing Tools

PG-1500	PROM programmer
PA-78P4916GF	PROM programmer adapter connected to PG-1500
PG-1500 controller Note 2	PG-1500 control program

Debugging Tools

IE-784000-R	78K/IV series common in-circuit emulator
IE-784000-R-BK	78K/IV series common break board
IE-784000-R-EM	78K/IV series common emulation board
IE-784915-R-EM1	μ PD784915 subseries evaluation emulation board
IE-78000-R-SV3	Interface adapter when an EWS is used as the host machine
IE-70000-98-IF-B	Interface adapter when PC-9800 series (except notebook PC) is used as the host
	machine
IE-70000-98N-IF	Interface adapter and cable when PC-9800 series notebook PC is used as the host
	machine
IE-70000-PC-IF-B	Interface adapter when IBM PC/AT™ is used as the host machine
EP-784915GF-R	μ PD784915 subseries common emulation probe
EV-9200GF-100	Conversion socket to be mounted on a target system board made for 100-pin plastic
	QFP
SM78K4Note 3	78K/IV series common system simulator
ID78K4Note 3	IE-784000-R integrated debugger
DF784915 ^{Note 4}	μ PD784915 subseries common device file

Real-time OS

RX78K/IVNote 4	78K/IV series common real-time OS
MX78K4Note 2	78K/IV series common OS

- Notes 1. PC-9800 series (MS-DOS™) based
 - IBM PC/AT and its compatible machines (PC DOS™, Windows™, MS-DOS, IBM DOS™) based
 - HP9000 series 700[™] (HP-UX[™]) based
 - SPARCstation[™] (SunOS[™]) based
 - NEWS™ (NEWS-OS™) based
 - 2. PC-9800 series (MS-DOS) based
 - IBM PC/AT and its compatible machines (PC DOS, Windows, MS-DOS, IBM DOS) based
 - 3. PC-9800 series (MS-DOS + Windows) based
 - IBM PC/AT and its compatible machines (PC DOS, Windows, MS-DOS, IBM DOS) based
 - HP9000 series 700 (HP-UX) based
 - SPARCstation (SunOS) based
 - 4. PC-9800 series (MS-DOS) based
 - IBM PC/AT and its compatible machines (PC DOS, Windows, MS-DOS, IBM DOS) based
 - HP9000 series 700 (HP-UX) based
 - SPARCstation (SunOS) based

Remark RA78K4, CC78K4, SM78K4, and ID78K4 are used in combination with DF784915.



★ APPENDIX B. RELATED DOCUMENTS

Documents related to device

Document Name μPD784915 subseries user's manual - Hardware μPD784915 subseries special function register table 78K/IV series user's manual - Instruction 78K/IV series instruction table 78K/IV series instruction set	Documer	Document Number	
	Japanese	English	
μ PD784915 subseries user's manual - Hardware	U10444J	U10444E	
μ PD784915 subseries special function register table	U10976J	_	
78K/IV series user's manual - Instruction	U10905J	IEU-1386	
78K/IV series instruction table	U10594J	_	
78K/IV series instruction set	U10595J	_	
μ PD784915 subseries application note	U11361J	Planned to	
		be published	
78K/IV series application note - Software fundamental	U10095J	_	

Documents related to development tools (user's manual)

Document Name		Document Number	
		Japanese	English
RA78K4 assembler package	Language	U11162J	_
	Operation	U11334J	U11334E
RA78K series structured assembler preprocessor		EEU-817	EEU-1402
CC78K4 series	Language	EEU-961	_
	Operation	EEU-960	_
CC78K series library source file		EEU-777	_
PG-1500 PROM programmer		EEU-651	EEU-1335
PG-1500 controller PC-9800 series (MS-DOS) based		EEU-704	EEU-1291
PG-1500 controller IBM PC series (PC DOS) based		EEU-5008	U10540E
IE-784000-R		EEU-5004	EEU-1534
IE-784915-R-EM1 EP-784915GF-R		U10931J	_
SM78K4 system simulator Windows based	Reference	U10093J	U10093E
SM78K series system simulator	External components user	U10092J	U10092E
	open interface specification		
ID78K4 integrated debugger Windows based	Reference	U10440J	U10440E

Documents related to embedded software (user's manual)

Document Name		Document Number	
		Japanese	English
RX78K/IV real-time OS	Fundamental	U10604J	_
	Installation	U10603J	_
	Debugger	U10364J	_

Caution The documents listed above are subject to change without notice. Be sure to use the latest document for designing.



Other related documents

Document Name	Document Number	
	Japanese	English
IC package manual	C10943X	
Semiconductor device mounting technology manual	C10535J	C10535E
Quality grade on NEC semiconductor devices	C11531J	IEI-1209
NEC semiconductor device reliability/quality control system	U10983J	U10983E
Electrostatic discharge (ESD) test	MEM-539	_
Semiconductor devices quality guarantee guide	MEI-603	MEI-1202
Microcomputer-related product guide (Products by other manufacturers)	U11416J	_

Caution The documents listed above are subject to change without notice. Be sure to use the latest document for designing.

[MEMO]

NOTES FOR CMOS DEVICES -

1) PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.



FIP is a trademark of NEC Corporation.

MS-DOS and Windows are trademarks of Microsoft Corporation.

IBM DOS, PC/AT, and PC DOS are trademarks of IBM Corporation.

HP9000 Series 700 and HP-UX are trademarks of Hewlett-Packard Company.

SPARCstation is a trademark of SPARC International, Inc.

SunOS ia a trademark of Sun Microsystems, Inc.

NEWS and NEW-OS are trademarks of Sony Corporation.

The documents referred to in this publication may include preliminary versions. However, preliminary versions are not marked as such.

The export of this product from Japan is regulated by the Japanese government. To export this product may be prohibited without governmental license, the need for which must be judged by the customer. The export or re-export of this product from a country other than Japan may also be prohibited without a license from that country. Please call an NEC sales representative.

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Corporation. NEC Corporation assumes no responsibility for any errors which may appear in this document.

NEC Corporation does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from use of a device described herein or any other liability arising from use of such device. No license, either express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC Corporation or others.

While NEC Corporation has been making continuous effort to enhance the reliability of its semiconductor devices, the possibility of defects cannot be eliminated entirely. To minimize risks of damage or injury to persons or property arising from a defect in an NEC semiconductor device, customers must incorporate sufficient safety measures in its design, such as redundancy, fire-containment, and anti-failure features.

NEC devices are classified into the following three quality grades:

"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic

equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster

systems, anti-crime systems, safety equipment and medical equipment (not specifically designed

for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life

support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.